



TS4621

High performance class G stereo headphone amplifier with I2C volume control

Features

- Power supply range: 2.3 V to 4.8 V
- 0.6 mA/channel quiescent current
- 2.1 mA current consumption with 100 μ W/channel (10 dB crest factor)
- 0.006% typical THD+N at 1 kHz
- 100 dB typical PSRR at 217 Hz
- 100 dB of SNR A-weighted at G = 0 dB
- Zero pop and click
- I²C interface for volume control
- Digital volume control range from -60 dB to +4 dB
- Independent right and left channel shutdown control
- Integrated high efficiency step-down converter
- Low software standby current: 5 μ A max
- Output-coupling capacitors removed
- Thermal shutdown
- Flip-chip package: 1.65 mm x 1.65 mm, 400 μ m pitch, 16 bumps

Applications

- Cellular phones, smart phones
- Mobile Internet devices
- PMP/MP3 players

Description

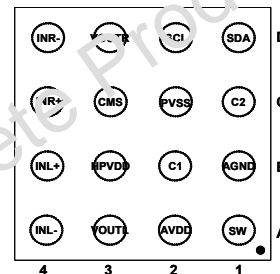
The TS4621 is a class G stereo headphone driver dedicated to high audio performance, high power efficiency and space-constrained applications.

It is based on the core technology of a low power dissipation amplifier combined with a high efficiency step-down DC/DC converter for supplying this amplifier.

TS4621BEIJT - flip-chip



Pinout (top view)



Balls are underneath

When powered by a battery, the internal step-down DC/DC converter generates the appropriate voltage to the amplifier depending on the amplitude of the audio signal to supply the headsets. It achieves a total 2.1 mA current consumption at 100 μ W output power (10 dB crest factor).

THD+N is 0.02 % maximum at 1 kHz and PSRR is 100 dB at 217 Hz, which ensures a high audio quality of the device in a wide range of environments.

The traditionally bulky output coupling capacitors can be removed.

A dedicated common-mode sense pin removes parasitic ground noise.

The TS4621 is designed to be used with an output serial resistor. It ensures unconditional stability over a wide range of capacitive loads.

The TS4621 is packaged in a tiny 16-bump flip-chip package with a pitch of 400 μ m.

Contents

1	Absolute maximum ratings and operating conditions	6
2	Typical application schematics	8
3	Electrical characteristics	10
4	Application information	25
4.1	I ² C bus interface	25
4.1.1	I ² C bus operation	25
4.1.2	Control register CR1 - address 1	27
4.1.3	Control register CR2 - address 2	28
4.1.4	Control register CR3 - address 3	28
4.1.5	Summary of output impedance	29
4.2	Wake-up and standby time definition	29
4.3	Overview of the class G, 2-level headphone amplifier	30
4.4	External component selection	32
4.4.1	Step-down inductor selection (L1)	32
4.4.2	Step-down output capacitor selection (Ct)	32
4.4.3	Full capacitive inverter capacitors selection (C12 and C _{ss})	33
4.4.4	Power supply decoupling capacitor selection (C _s)	33
4.4.5	Input coupling capacitor selection (C _{in})	33
4.4.6	Low-pass output filter (R _{out} and C _{out}) and IEC 61000-4-2 ESD protection	34
4.4.7	Integrated input low-pass filter	35
4.5	Single-ended input configuration	35
4.5.1	Layout recommendations for single-ended operation	37
4.6	Startup phase	39
4.6.1	Auto zero technology	39
4.6.2	Input impedance	39
4.7	Layout recommendations	39
4.7.1	Common mode sense layout	40
4.8	Demonstration board	41

5	Package information	43
6	Ordering information	45
7	Revision history	46

Obsolete Product(s) - Obsolete Product(s)

List of figures

Figure 1.	Typical application schematics for the TS4621	8
Figure 2.	SCL and SDA timing diagram	12
Figure 3.	Start and stop condition timing diagram	12
Figure 4.	Current consumption vs. power supply voltage	13
Figure 5.	Standby current consumption vs. power supply voltage	13
Figure 6.	Maximum output power vs. load in-phase	13
Figure 7.	Maximum output power vs. load out-of-phase	13
Figure 8.	Maximum output power vs. power supply voltage, $R_L = 16\ \Omega$	13
Figure 9.	Maximum output power vs. power supply voltage, $R_L = 32\ \Omega$	13
Figure 10.	Maximum output power vs. power supply voltage, $R_L = 47\ \Omega$	14
Figure 11.	Maximum output voltage vs. power supply voltage, in-phase	14
Figure 12.	Maximum output voltage vs. power supply voltage, out-of-phase	14
Figure 13.	Current consumption vs. total output power, $R_L = 16\ \Omega$	14
Figure 14.	Current consumption vs. total output power, $R_L = 32\ \Omega$	14
Figure 15.	Current consumption vs. total output power, $R_L = 47\ \Omega$	14
Figure 16.	Current consumption vs. total output power	15
Figure 17.	Power dissipation vs. total output power	15
Figure 18.	Output impedance vs. frequency in HiZ mode	15
Figure 19.	Differential input impedance vs. gain	15
Figure 20.	THD+N vs. output power $R_L = 16\ \Omega$, in-phase, $V_{CC} = 2.5\text{ V}$	15
Figure 21.	THD+N vs. output power $R_L = 16\ \Omega$, out-of-phase, $V_{CC} = 2.5\text{ V}$	15
Figure 22.	THD+N vs. output power $R_L = 16\ \Omega$, in-phase, $V_{CC} = 3.6\text{ V}$	16
Figure 23.	THD+N vs. output power $R_L = 16\ \Omega$, out-of-phase, $V_{CC} = 3.6\text{ V}$	16
Figure 24.	THD+N vs. output power $R_L = 16\ \Omega$, in-phase, $V_{CC} = 4.8\text{ V}$	16
Figure 25.	THD+N vs. output power $R_L = 16\ \Omega$, out-of-phase, $V_{CC} = 4.8\text{ V}$	16
Figure 26.	THD+N vs. output power $R_L = 32\ \Omega$, in-phase, $V_{CC} = 2.5\text{ V}$	16
Figure 27.	THD+N vs. output power $R_L = 32\ \Omega$, out-of-phase, $V_{CC} = 2.5\text{ V}$	16
Figure 28.	THD+N vs. output power $R_L = 32\ \Omega$, in-phase, $V_{CC} = 3.6\text{ V}$	17
Figure 29.	THD+N vs. output power $R_L = 32\ \Omega$, out-of-phase, $V_{CC} = 3.6\text{ V}$	17
Figure 30.	THD+N vs. output power $R_L = 32\ \Omega$, in-phase, $V_{CC} = 4.8\text{ V}$	17
Figure 31.	THD+N vs. output power $R_L = 32\ \Omega$, out-of-phase, $V_{CC} = 4.8\text{ V}$	17
Figure 32.	THD+N vs. output power $R_L = 47\ \Omega$, in-phase, $V_{CC} = 2.5\text{ V}$	17
Figure 33.	THD+N vs. output power $R_L = 47\ \Omega$, out-of-phase, $V_{CC} = 2.5\text{ V}$	17
Figure 34.	THD+N vs. output power $R_L = 47\ \Omega$, in-phase, $V_{CC} = 3.6\text{ V}$	18
Figure 35.	THD+N vs. output power $R_L = 47\ \Omega$, out-of-phase, $V_{CC} = 3.6\text{ V}$	18
Figure 36.	THD+N vs. output power $R_L = 47\ \Omega$, in-phase, $V_{CC} = 4.8\text{ V}$	18
Figure 37.	THD+N vs. output power $R_L = 47\ \Omega$, out-of-phase, $V_{CC} = 4.8\text{ V}$	18
Figure 38.	THD+N vs. frequency $R_L = 16\ \Omega$, in-phase, $V_{CC} = 2.5\text{ V}$	18
Figure 39.	THD+N vs. frequency $R_L = 16\ \Omega$, out-of-phase, $V_{CC} = 2.5\text{ V}$	18
Figure 40.	THD+N vs. frequency $R_L = 16\ \Omega$, in-phase, $V_{CC} = 3.6\text{ V}$	19
Figure 41.	THD+N vs. frequency $R_L = 16\ \Omega$, out-of-phase, $V_{CC} = 3.6\text{ V}$	19
Figure 42.	THD+N vs. frequency $R_L = 16\ \Omega$, in-phase, $V_{CC} = 4.8\text{ V}$	19
Figure 43.	THD+N vs. frequency $R_L = 16\ \Omega$, out-of-phase, $V_{CC} = 4.8\text{ V}$	19
Figure 44.	THD+N vs. frequency $R_L = 32\ \Omega$, in-phase, $V_{CC} = 2.5\text{ V}$	19
Figure 45.	THD+N vs. frequency $R_L = 32\ \Omega$, out-of-phase, $V_{CC} = 2.5\text{ V}$	19
Figure 46.	THD+N vs. frequency $R_L = 32\ \Omega$, in-phase, $V_{CC} = 3.6\text{ V}$	20
Figure 47.	THD+N vs. frequency $R_L = 32\ \Omega$, out-of-phase, $V_{CC} = 3.6\text{ V}$	20
Figure 48.	THD+N vs. frequency $R_L = 32\ \Omega$, in-phase, $V_{CC} = 4.8\text{ V}$	20

Figure 49.	THD+N vs. frequency $R_L = 32\ \Omega$, out-of-phase, $V_{CC} = 4.8\text{ V}$	20
Figure 50.	THD+N vs. frequency $R_L = 47\ \Omega$, in-phase, $V_{CC} = 2.5\text{ V}$	20
Figure 51.	THD+N vs. frequency $R_L = 47\ \Omega$, out-of-phase, $V_{CC} = 2.5\text{ V}$	20
Figure 52.	THD+N vs. frequency $R_L = 47\ \Omega$, in-phase, $V_{CC} = 3.6\text{ V}$	21
Figure 53.	THD+N vs. frequency $R_L = 47\ \Omega$, out-of-phase, $V_{CC} = 3.6\text{ V}$	21
Figure 54.	THD+N vs. frequency $R_L = 47\ \Omega$, in-phase, $V_{CC} = 4.8\text{ V}$	21
Figure 55.	THD+N vs. frequency $R_L = 47\ \Omega$, out-of-phase, $V_{CC} = 4.8\text{ V}$	21
Figure 56.	THD+N vs. frequency $R_L = 10\text{ k}\Omega$	21
Figure 57.	THD+N vs. frequency $R_L = 600\ \Omega$	21
Figure 58.	THD+N vs. output voltage $R_L = 10\text{ k}\Omega$	22
Figure 59.	THD+N vs. output voltage $R_L = 600\ \Omega$	22
Figure 60.	THD+N vs. input voltage, HiZ left and right	22
Figure 61.	CMRR vs. frequency	22
Figure 62.	PSRR vs. frequency $V_{CC} = 2.5\text{ V}$	22
Figure 63.	PSRR vs. frequency $V_{CC} = 3.6\text{ V}$	22
Figure 64.	PSRR vs. frequency $V_{CC} = 4.8\text{ V}$	23
Figure 65.	Output signal spectrum	23
Figure 66.	Crosstalk vs. frequency $R_L = 16\ \Omega$	23
Figure 67.	Crosstalk vs. frequency $R_L = 32\ \Omega$	23
Figure 68.	Crosstalk vs. frequency $R_L = 47\ \Omega$	23
Figure 69.	Crosstalk vs. frequency $R_L = 10\text{ k}\Omega$	23
Figure 70.	Wake-up time	24
Figure 71.	Shutdown time	24
Figure 72.	I ² C write operations	26
Figure 73.	I ² C read operations	27
Figure 74.	TS4621 architecture	30
Figure 75.	Efficiency comparison	31
Figure 76.	Class G operating with a music sample	31
Figure 77.	Typical application schematic with IEC 61000-4-2 ESD protection	35
Figure 78.	Single-ended input configuration1	36
Figure 79.	Single-ended input configuration 2	36
Figure 80.	Incorrect ground connection for single-ended option	37
Figure 81.	Correct ground connection for single-ended option	38
Figure 82.	Common mode sense layout example	40
Figure 83.	Demonstration board schematic	41
Figure 84.	Copper layers	42
Figure 85.	Copper layer and overlay layers	42
Figure 86.	TS4621 footprint recommendation	43
Figure 87.	Pinout	43
Figure 88.	Marking (top view)	44
Figure 89.	Flip-chip - 16 bumps	44
Figure 90.	Device orientation in tape pocket	44

1 Absolute maximum ratings and operating conditions

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage ⁽¹⁾ during 1ms.	5.5	V
V_{in+}, V_{in-}	Input voltage referred to ground	+/- 1.2	V
T_{stg}	Storage temperature	-65 to +150	°C
T_j	Maximum junction temperature ⁽²⁾	150	°C
R_{thja}	Thermal resistance junction to ambient ⁽³⁾	200	°C/W
P_d	Power dissipation	Internally limited ⁽⁴⁾	
ESD	Human body model (HBM) ⁽⁵⁾ All pins VOUTR, VOUTL vs. AGND	2 4	kV
	Machine model (MM), min. value ⁽⁶⁾	100	V
	Charge device model (CDM) All pins VOUTR, VOUTL	500 750	V
	IEC61000-4-2 level 4, contact ⁽⁷⁾ IEC61000-4-2 level 4, air discharge ⁽⁷⁾	+/- 8 +/- 15	kV
	Lead temperature (soldering, 10 sec)	260	°C

1. All voltage values are measured with respect to the ground pin.
2. Thermal shutdown is activated when maximum junction temperature is reached.
3. The device is protected from over-temperature by a thermal shutdown mechanism, active at 150° C.
4. Exceeding the power derating curves for long periods may provoke abnormal operation.
5. Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5 k Ω resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.
6. Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of connected pin combinations while the other pins are floating.
7. The measurement is performed on an evaluation board, with ESD protection EMIF02-AV01F3.

Table 2. Operating conditions

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	2.3 to 4.8	V
HPVDD	internal step-down DC output voltages High rail voltage Low rail voltage	1.9 1.2	V
SDA, SCL	Input voltage range	GND to V_{CC}	V
R_L	Load resistor	≥ 16	Ω
C_L	Load capacitor Serial resistor of 12 Ω minimum, $R_L \geq 16 \Omega$	0.8 to 100	nF
T_{oper}	Operating free air temperature range	-40 to +85	$^{\circ}\text{C}$
R_{thja}	Flip-chip thermal resistance junction to ambient	90	$^{\circ}\text{C/W}$

2 Typical application schematics

Figure 1. Typical application schematics for the TS4621

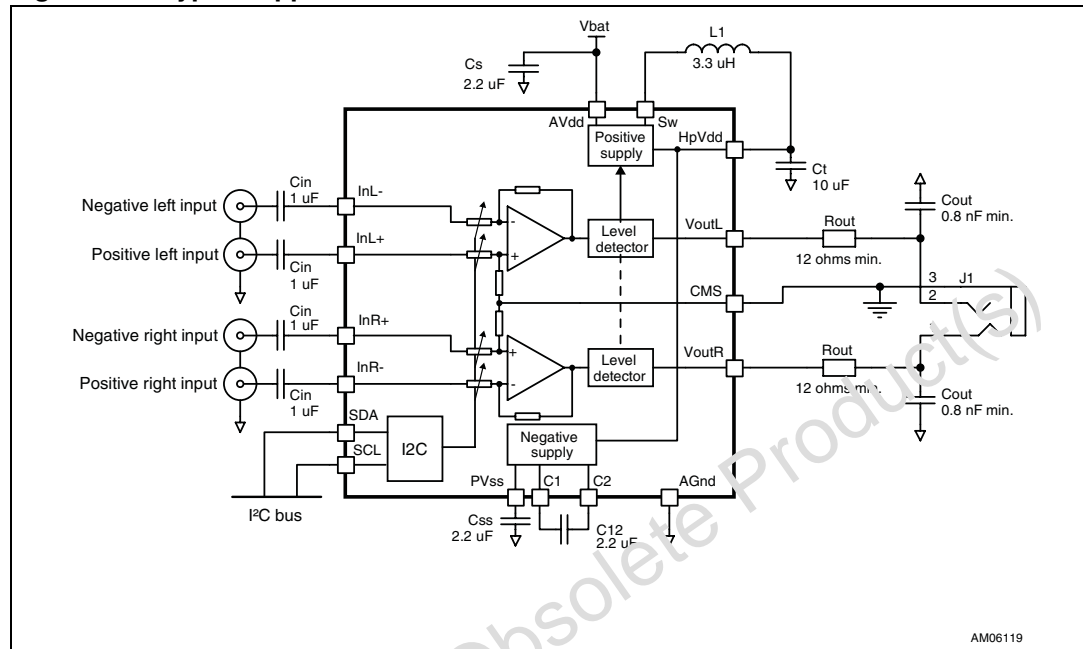


Table 3. TS4621 pin description

Pin number	Pin name	Pin definition
A1	SW	Switching node of the buck converter
A2	AVDD	Analog supply voltage, connect to battery
A3	VOUTL	Output signal for left audio channel
A4	INL-	Negative input signal for left audio channel
B1	AGND	Device ground
B2	C1	Flying capacitor terminal for internal negative supply generator
B3	HPVDD	Buck converter output, power supply for amplifier
B4	INL+	Positive input signal for left audio channel
C1	C2	Flying capacitor terminal for internal negative supply generator
C2	PVSS	Negative supply generator output
C3	CMS	Common mode sense, to be connected as close as possible to the ground of headphone/line out plug
C4	INR+	Positive input signal for right audio channel
D1	SDA	I ² C data signal, up to V _{CC} tolerant input
D2	SCL	I ² C clock signal, up to V _{CC} tolerant input
D3	VOUTR	Output signal for right audio channel
D4	INR-	Negative input signal for right audio channel

Table 4. TS4621 component description⁽¹⁾

Component	Value	Description
C _s	2.2 μF	Decoupling capacitors for V _{CC} . A 2.2 μF capacitor is sufficient for proper decoupling of the TS4621. An X5R dielectric and 10 V rating voltage is recommended to minimize ΔC/ΔV when V _{CC} = 4.8 V. Must be placed as close as possible to the TS4621 to minimize parasitic inductance and resistance.
C _{I2}	2.2 μF	Capacitor for internal negative power supply operation. An X5R dielectric and 6.3 V rating voltage is recommended to minimize ΔC/ΔV when HPVDD = 1.9 V. Must be placed as close as possible to the TS4621 to minimize parasitic inductance and resistance.
C _{SS}	2.2 μF	Filtering capacitor for internal negative power supply. An X5R dielectric and 6.3 V rating voltage is recommended to minimize ΔC/ΔV when HPVDD = 1.9 V.
C _{in}	$C_{in} = \frac{1}{2 \times \pi \times R_{in} \times F_c}$	Input coupling capacitor that forms with R _{in} ≈ R _{ind} /2 a first-order high-pass filter with a -3 dB cut-off frequency F _c . For example, at maximum gain G = 4 dB, R _{in} = 12.5 kΩ, C _{in} = 1 μF, therefore F _c = 13 Hz.
C _{out}	0.8 to 100 nF	Output capacitor of 0.8 nF minimum to 100 nF maximum. This capacitor is mandatory for operation of the TS4621.
R _{out}	12 Ω min.	Output resistor in-series with the TS4621 output. This 12 Ω minimum resistor is mandatory for operation of the TS4621.
L1	3.3 μH	Inductor for internal DC/DC step-down converter. References of inductors: refer to Section 4.4.1 for more information.
C _t	10 μF	Tank capacitor for internal DC/DC step-down converter. An X5R dielectric and 6.3 V rating voltage is recommended to minimize ΔC/ΔV when HPVDD = 1.9 V. Refer to Section 4.4.2 for more information.

1. Refer to [Section 4.4](#) for a complete description of each component.

3 Electrical characteristics

Table 5. Electrical characteristics of the I²C interface
for $V_{CC} = +3.6\text{ V}$, $AGND = 0\text{ V}$, $T_{amb} = 25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{IL}	Low level input voltage on SDA, SCL pins			0.6	V
V_{IH}	High level input voltage on SDA, SCL pins	1.2			V
V_{OL}	Low level output voltage, SDA pin, $I_{sink} = 3\text{ mA}$			0.4	V
I_{in}	Input current on SDA, SCL		$\frac{V_{SDA, SCL}}{600\text{ k}\Omega}$	10	μA

Table 6. Electrical characteristics of the amplifier
for $V_{CC} = +3.6\text{ V}$, $AGND = 0\text{ V}$, $R_L = 32\ \Omega + 15\ \Omega$, $T_{amb} = 25^{\circ}\text{C}$
(unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
I_{CC}	Quiescent supply current, no input signal, both channels enabled		1.2	1.5	mA
I_s	Supply current, with input modulation, both channels enabled, $HPVDD = 1.2\text{ V}$, output power per channel, $f = 1\text{ kHz}$ Pout = 100 μW at 3 dB crest factor Pout = 500 μW at 3 dB crest factor Pout = 1 mW at 3 dB crest factor Pout = 100 μW at 10 dB crest factor Pout = 500 μW at 10 dB crest factor Pout = 1 mW at 10 dB crest factor		2.3 3.7 4.7 2.1 3.1 3.9	3.5 5 6.5	mA
I_{STBY}	Standby current, no input signal, I ² C CR1 = 01h $V_{SDA} = 0\text{ V}$, $V_{SCL} = 0\text{ V}$		0.6	5	μA
V_{in}	Input differential voltage range ⁽¹⁾			1	V_{rms}
V_{oo}	Output offset voltage No input signal	-500		+500	μV
V_{out}	Maximum output voltage, in-phase signals $R_L = 16\ \Omega$, THD+N = 1% max, $f = 1\text{ kHz}$ $R_L = 47\ \Omega$, THD+N = 1% max, $f = 1\text{ kHz}$ $R_L = 10\text{ k}\Omega$, $R_s = 15\ \Omega$, $C_L = 1\text{ nF}$, THD+N = 1% max, $f = 1\text{ kHz}$	0.6 1.0 1.0	0.8 1.1 1.3		V_{rms}
THD+N	Total harmonic distortion + noise, $G = 0\text{ dB}$ $V_{out} = 700\text{ mV}_{rms}$, $F = 1\text{ kHz}$ $V_{out} = 700\text{ mV}_{rms}$, $20\text{ Hz} < F < 20\text{ kHz}$		0.006 0.05	0.02	%
PSRR	Power supply rejection ratio ⁽¹⁾ , $V_{ripple} = 200\text{ mV}_{pp}$, grounded inputs $F = 217\text{ Hz}$, $G = 0\text{ dB}$, $R_L \geq 16\ \Omega$ $F = 10\text{ kHz}$, $G = 0\text{ dB}$, $R_L \geq 16\ \Omega$	90	100 70		dB

Table 6. Electrical characteristics of the amplifier
for $V_{CC} = +3.6\text{ V}$, $AGND = 0\text{ V}$, $R_L = 32\ \Omega + 15\ \Omega$, $T_{amb} = 25^\circ\text{ C}$
(unless otherwise specified) (continued)

Symbol	Parameter	Min.	Typ.	Max.	Unit
CMRR	Common mode rejection ratio F = 1 kHz, G = 0 dB, $V_{ic} = 200\text{ mV}_{pp}$ F = 20 Hz to 20 kHz, G = 0 dB, $V_{ic} = 200\text{ mV}_{pp}$		65 45		dB
Crosstalk	Channel separation $R_L = 32\ \Omega + 15\ \Omega$, G = 0 dB, F = 1 kHz, $P_o = 10\text{ mW}$ $R_L = 10\text{ k}\Omega$, G = 0 dB, F = 1 kHz, $V_{out} = 1\text{ V}_{rms}$	60 80	100 110		dB
SNR	Signal-to-noise ratio, A-weighted, $V_{out} = 1\text{ V}_{rms}$, THD+N < 1%, F = 1 kHz ⁽¹⁾ G = +4 dB G = +0 dB	99 100			dB
ONoise	Output noise voltage, A-weighted ⁽¹⁾ G = +4 dB G = +0 dB		9 9	11	μV_{rms}
G	Gain range with gain (dB) = $20 \times \log[(V_{out}/R)/(I_{in}/R+ - I_{in}/R-)]$	60		+4	dB
Mute	$I_{in}/R+ - I_{in}/R- = 1\text{ V}_{rms}$			-80	dB
-	Gain step size error	-0.5		+0.5	step-size
-	Gain error (G = +4 dB)	-0.45		+0.42	dB
R_{indiff}	Differential input impedance	25	34		k Ω
	Input impedance during wake-up phase (referred to ground)		2		k Ω
Z_{out}	Output impedance when $CR1 = 0\text{ ohm}$ (negative supply is ON and amplifier output stages are OFF) ⁽¹⁾ F < 40 kHz F = 6 MHz F = 36 MHz	10 500 75			k Ω Ω Ω
t_{wu}	Wake-up time ⁽²⁾		12	16	ms
t_{stby}	Standby time		100		μs
t_{atk}	Attack time. Setup time between low rail and high rail voltages of internal step-down DC/DC converter		100		μs
t_{dcy}	Decay time		50		ms

1. Guaranteed by design and parameter correlation.

2. Refer to the application information in [Section 4.2 on page 29](#).

Table 7. Timing characteristics of the I²C interface for I²C interface signals over recommended operating conditions (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
f_{SCL}	Frequency, SCL			400	kHz
$t_{d(H)}$	Pulse duration, SCL high	0.6			μ s
$t_{d(L)}$	Pulse duration, SCL low	1.3			μ s
t_{st1}	Setup time, SDA to SCL	100			ns
t_{h1}	Hold time, SCL to SDA	0			ns
t_f	Bus free time between stop and start condition	1.3			μ s
t_{st2}	Setup time, SCL to start condition	0.6			μ s
t_{h2}	Hold time, start condition to SCL	0.6			μ s
t_{st3}	Setup time, SCL to stop condition	0.6			μ s

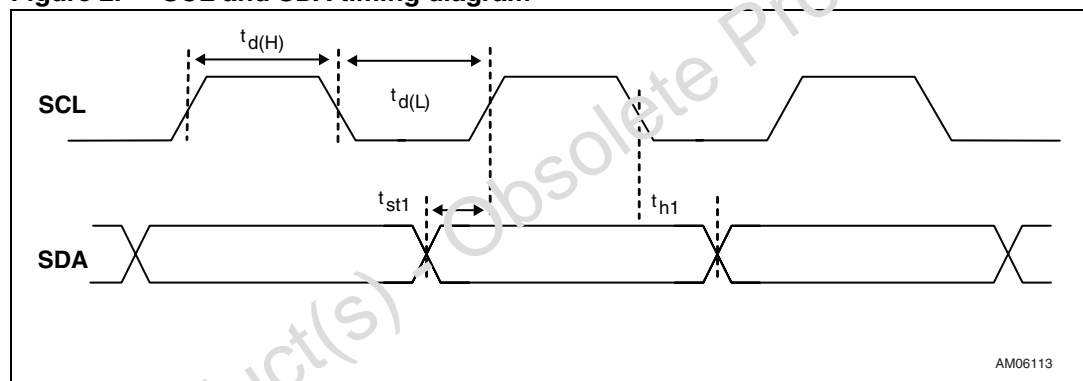
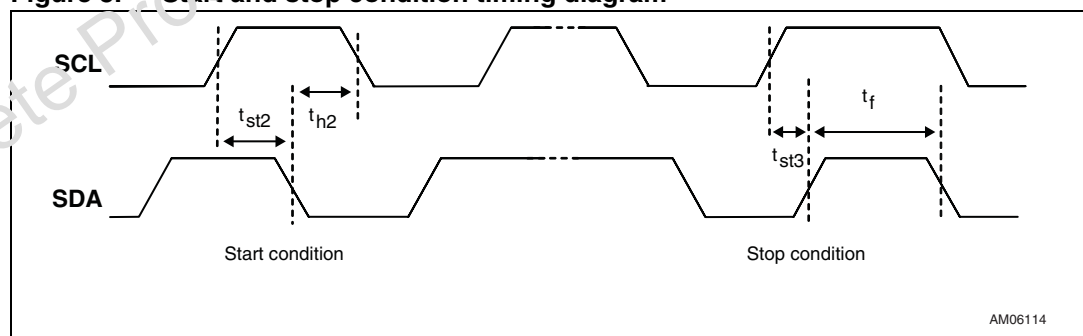
Figure 2. SCL and SDA timing diagram**Figure 3. Start and stop condition timing diagram**

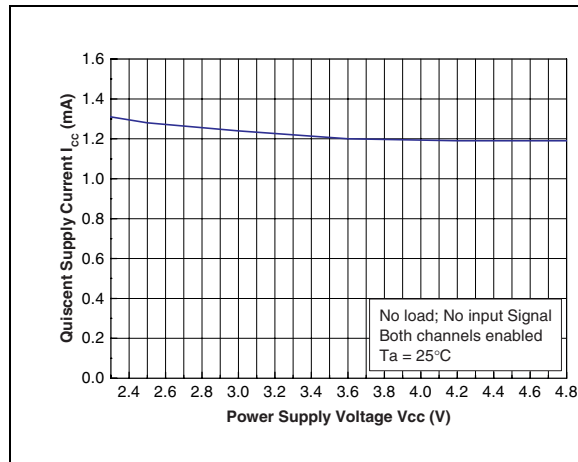
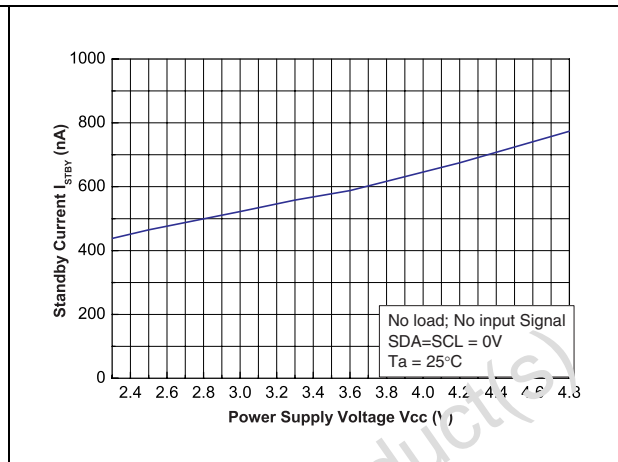
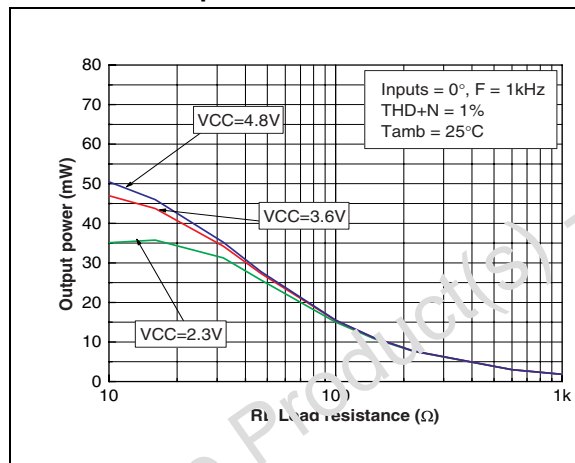
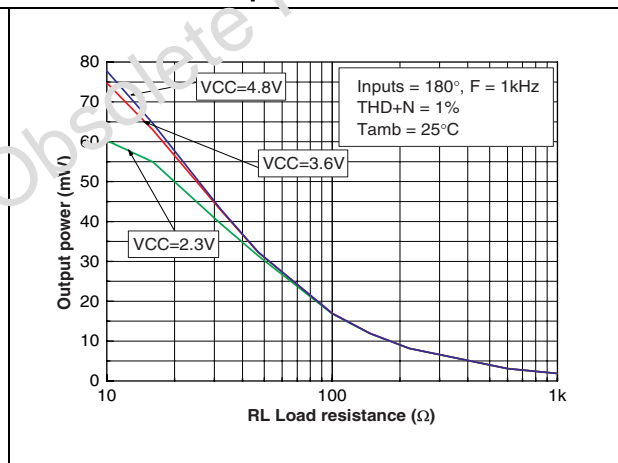
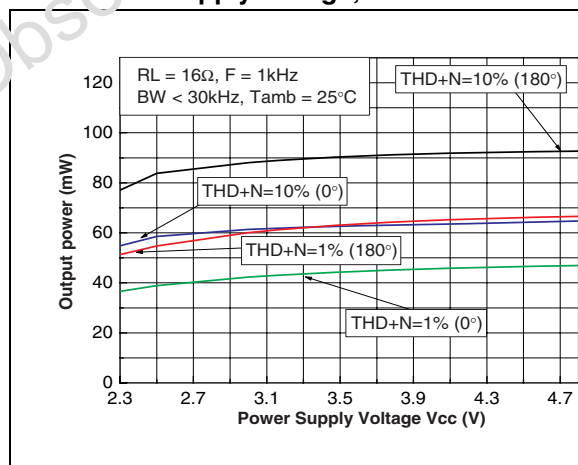
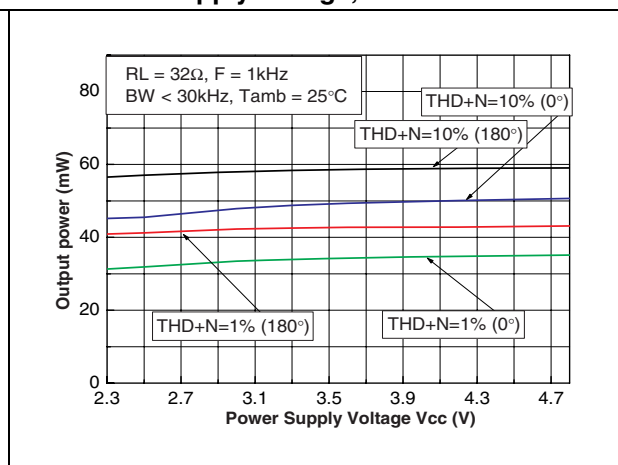
Figure 4. Current consumption vs. power supply voltage**Figure 5. Standby current consumption vs. power supply voltage****Figure 6. Maximum output power vs. load in-phase****Figure 7. Maximum output power vs. load out-of-phase****Figure 8. Maximum output power vs. power supply voltage, RL = 16 Ω****Figure 9. Maximum output power vs. power supply voltage, RL = 32 Ω**

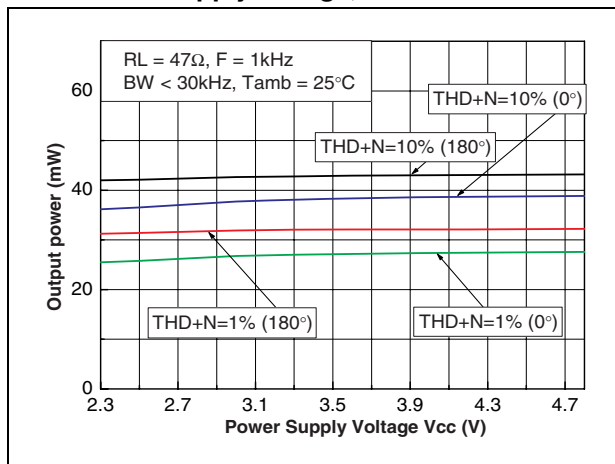
Figure 10. Maximum output power vs. power supply voltage, $R_L = 47\ \Omega$ 

Figure 11. Maximum output voltage vs. power supply voltage, in-phase

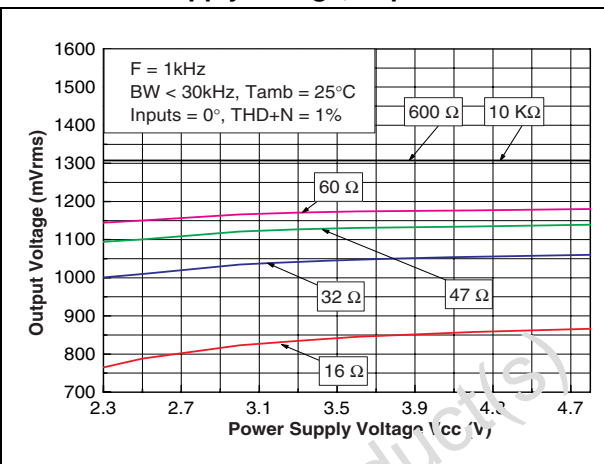


Figure 12. Maximum output voltage vs. power supply voltage, out-of-phase

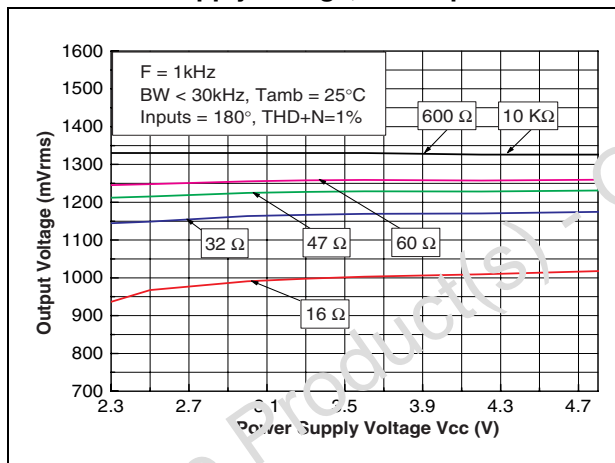
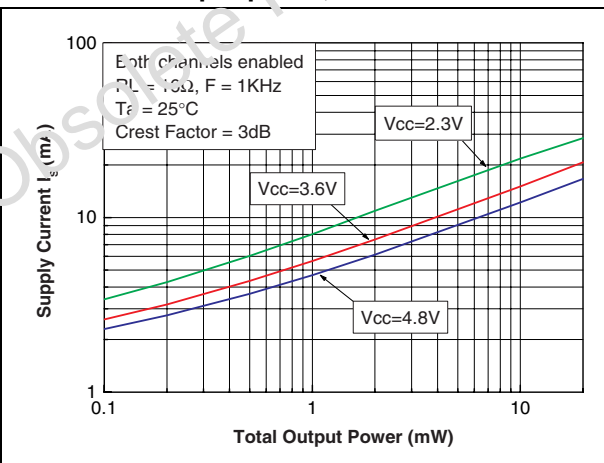
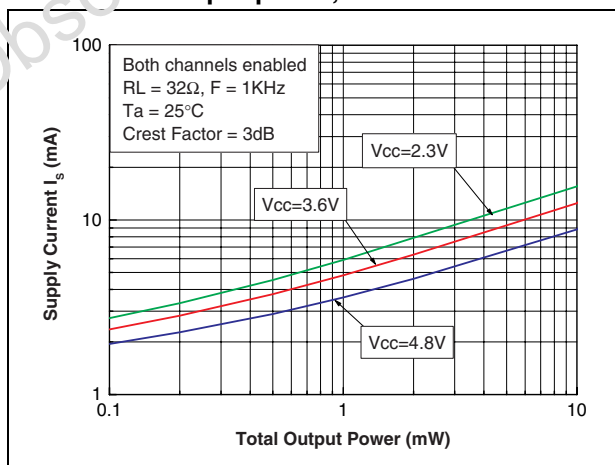
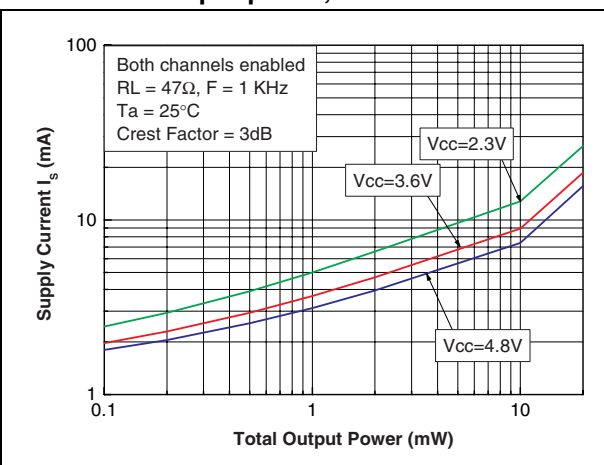
Figure 13. Current consumption vs. total output power, $R_L = 16\ \Omega$ Figure 14. Current consumption vs. total output power, $R_L = 32\ \Omega$ Figure 15. Current consumption vs. total output power, $R_L = 47\ \Omega$ 

Figure 16. Current consumption vs. total output power

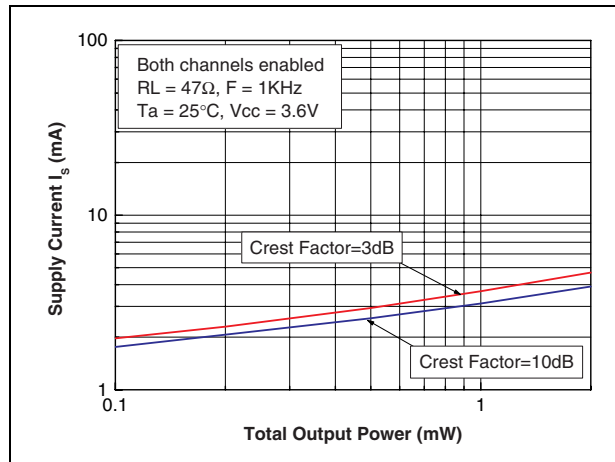


Figure 17. Power dissipation vs. total output power

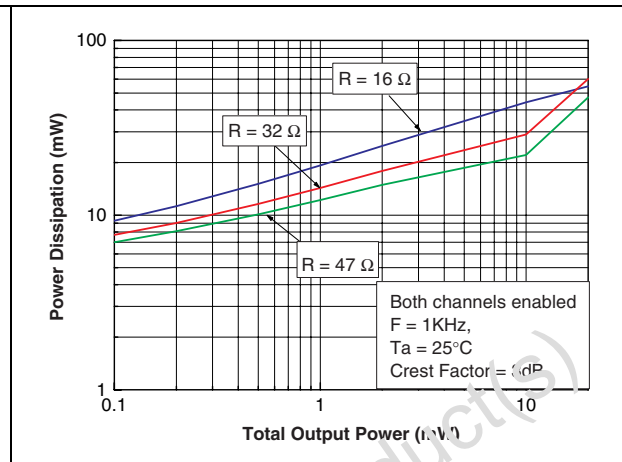


Figure 18. Output impedance vs. frequency in HiZ mode

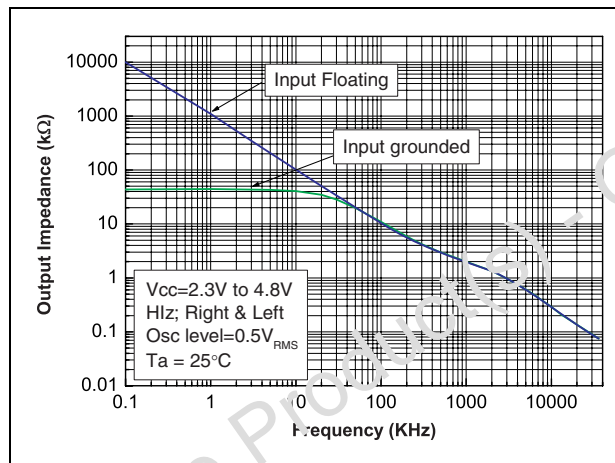


Figure 19. Differential input impedance vs. gain

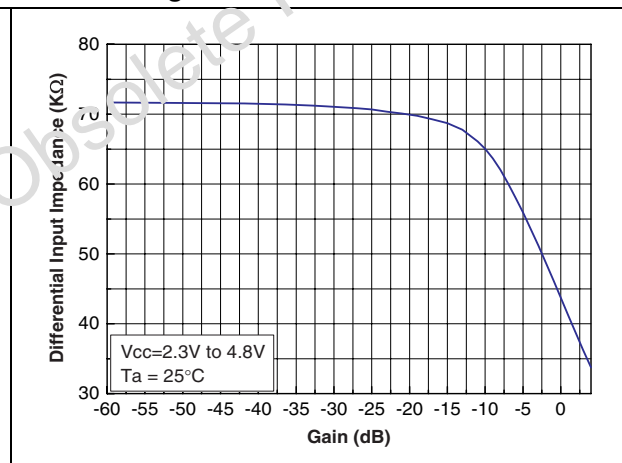
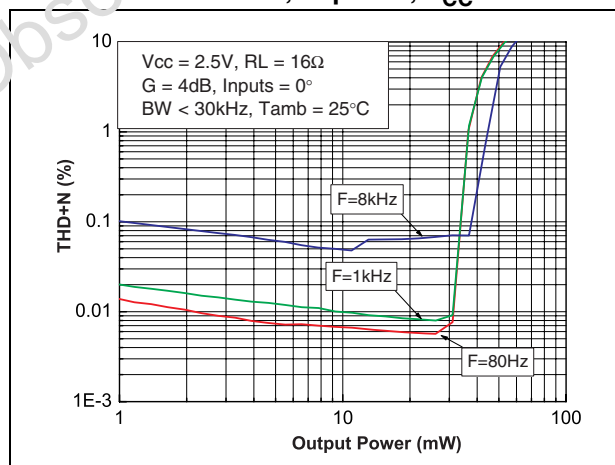
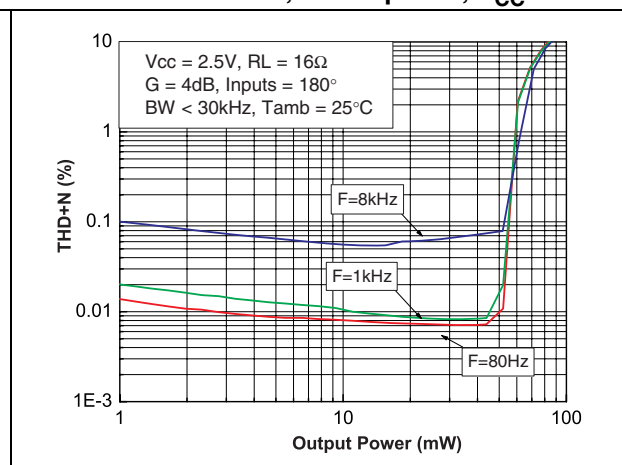
Figure 20. THD+N vs. output power
 $R_L = 16\Omega$ in-phase, $V_{CC} = 2.5\text{V}$ Figure 21. THD+N vs. output power
 $R_L = 16\Omega$ out-of-phase, $V_{CC} = 2.5\text{V}$ 

Figure 22. THD+N vs. output power
RL = 16 Ω in-phase, V_{CC} = 3.6 V

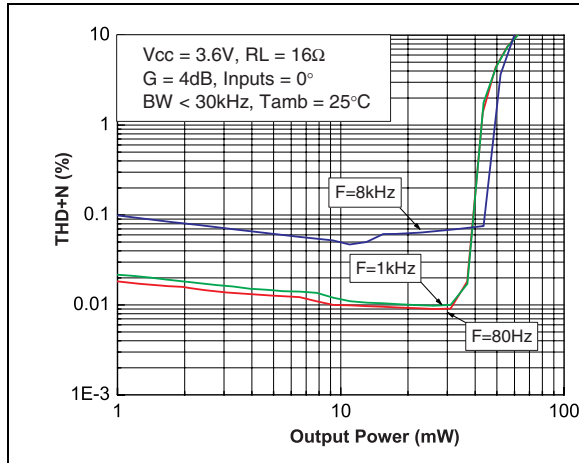


Figure 23. THD+N vs. output power
RL = 16 Ω out-of-phase, V_{CC} = 3.6 V

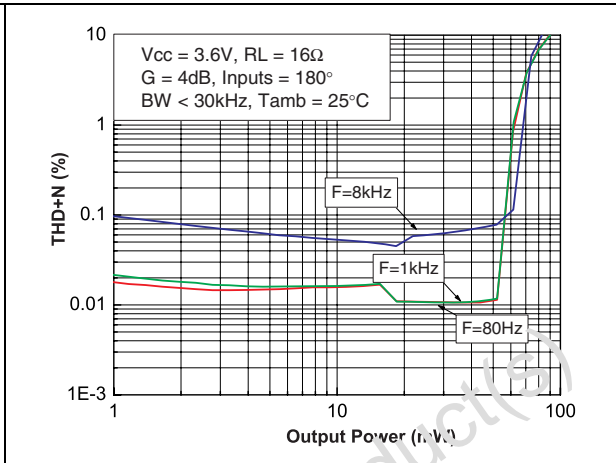


Figure 24. THD+N vs. output power
RL = 16 Ω in-phase, V_{CC} = 4.8 V

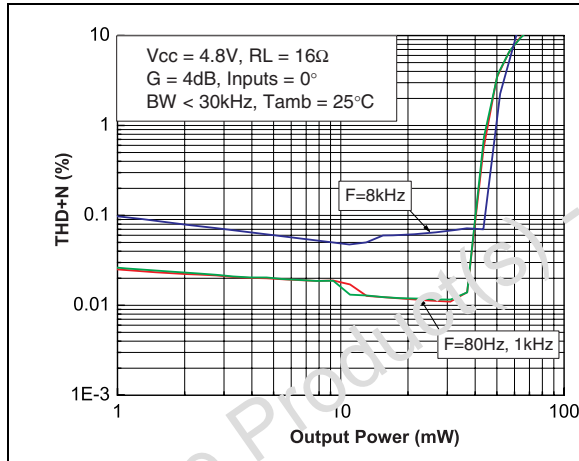


Figure 25. THD+N vs. output power
RL = 16 Ω out-of-phase, V_{CC} = 4.8 V

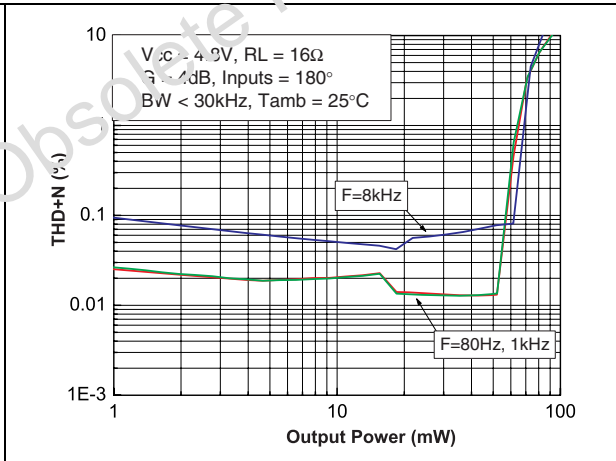


Figure 26. THD+N vs. output power
RL = 32 Ω in-phase, V_{CC} = 2.5 V

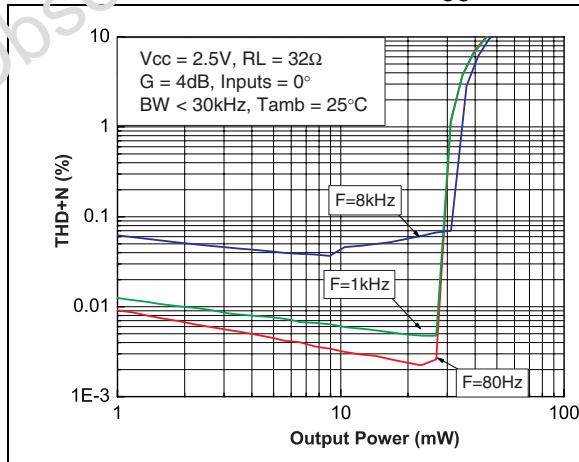


Figure 27. THD+N vs. output power
RL = 32 Ω out-of-phase, V_{CC} = 2.5 V

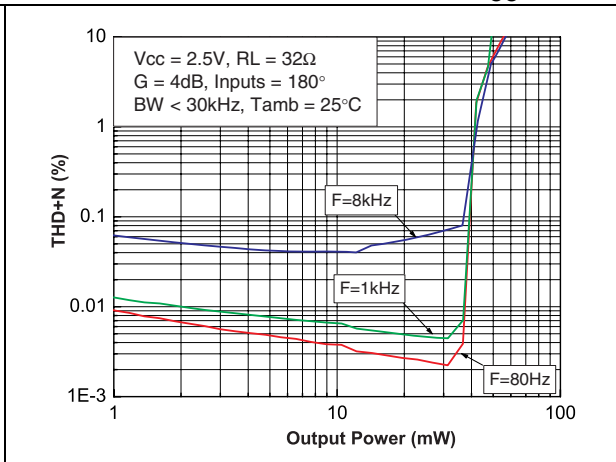


Figure 28. THD+N vs. output power
 $RL = 32\ \Omega$ in-phase, $V_{CC} = 3.6\ V$

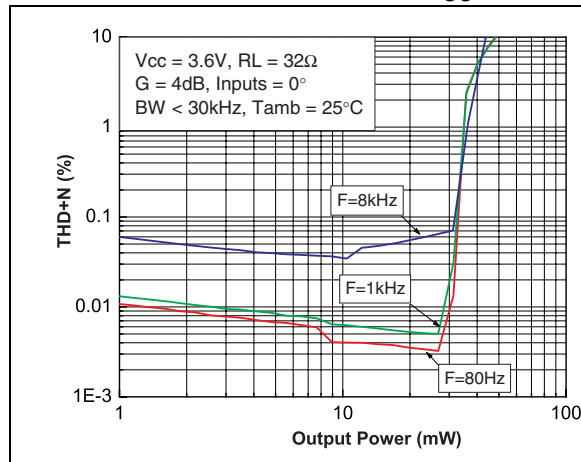


Figure 29. THD+N vs. output power
 $RL = 32\ \Omega$ out-of-phase, $V_{CC} = 3.6\ V$

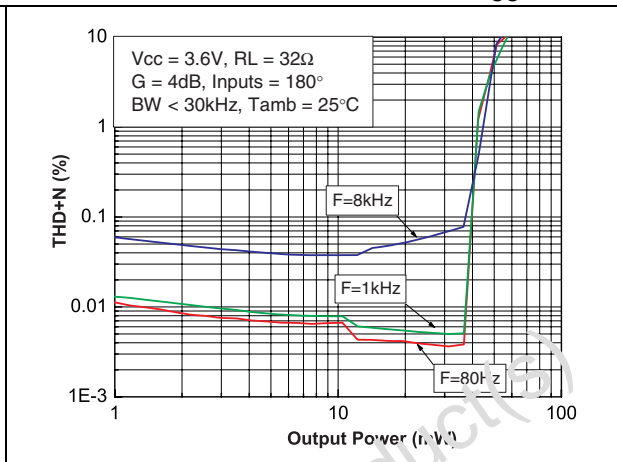


Figure 30. THD+N vs. output power
 $RL = 32\ \Omega$ in-phase, $V_{CC} = 4.8\ V$

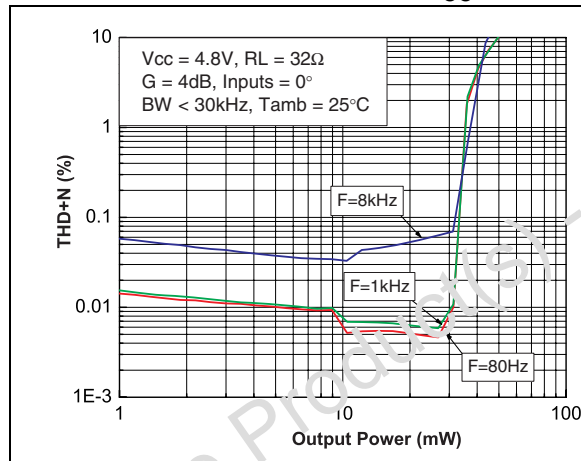


Figure 31. THD+N vs. output power
 $RL = 32\ \Omega$ out-of-phase, $V_{CC} = 4.8\ V$

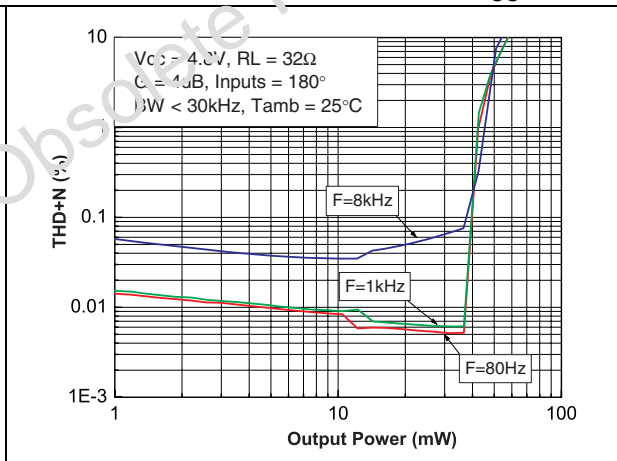


Figure 32. THD+N vs. output power
 $RL = 47\ \Omega$ in-phase, $V_{CC} = 2.5\ V$

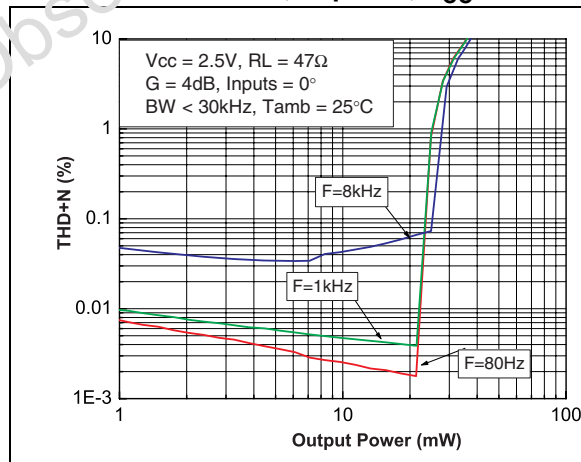


Figure 33. THD+N vs. output power
 $RL = 47\ \Omega$ out-of-phase, $V_{CC} = 2.5\ V$

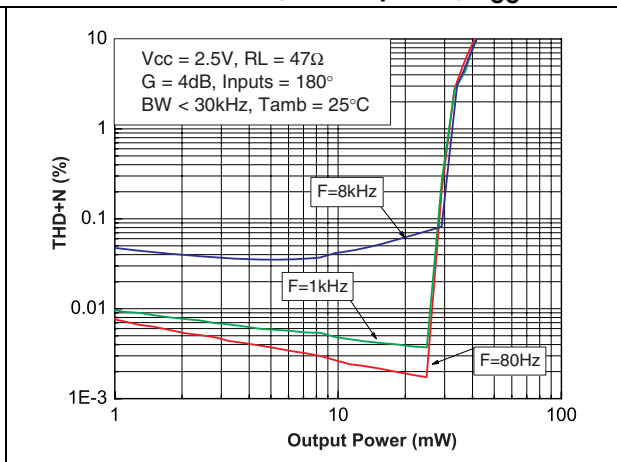


Figure 34. THD+N vs. output power
 $RL = 47\ \Omega$ in-phase, $V_{CC} = 3.6\ V$

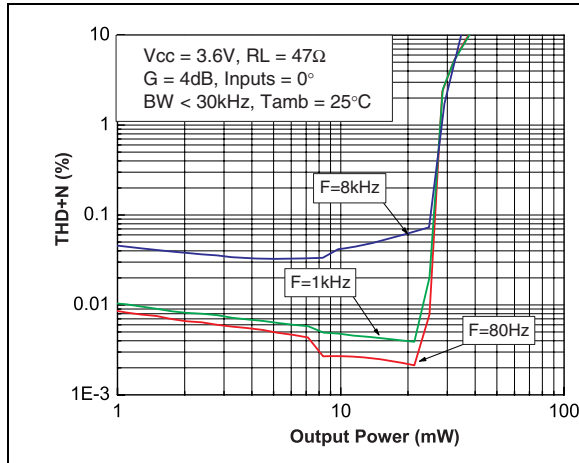


Figure 35. THD+N vs. output power
 $RL = 47\ \Omega$ out-of-phase, $V_{CC} = 3.6\ V$

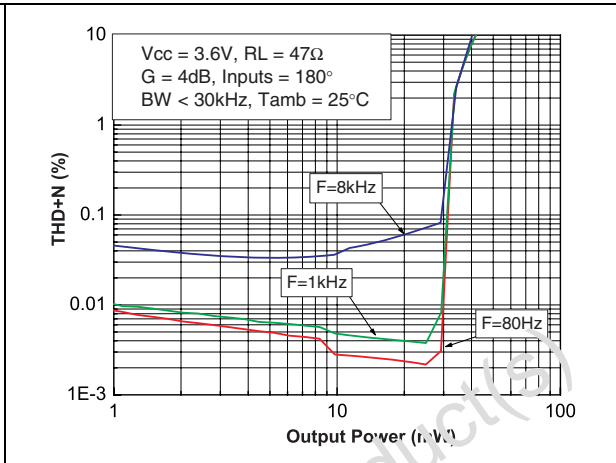


Figure 36. THD+N vs. output power
 $RL = 47\ \Omega$ in-phase, $V_{CC} = 4.8\ V$

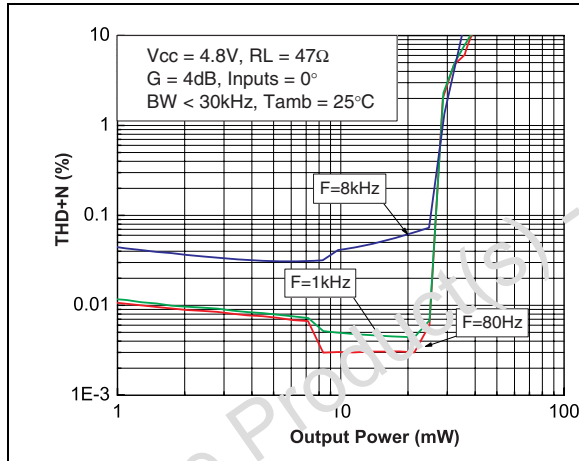


Figure 37. THD+N vs. output power
 $RL = 47\ \Omega$ out-of-phase, $V_{CC} = 4.8\ V$

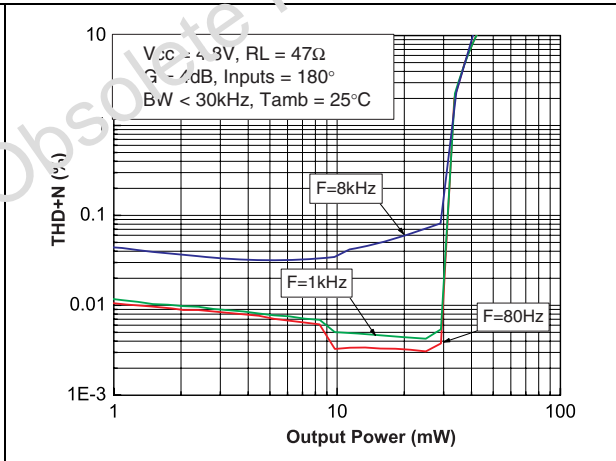


Figure 38. THD+N vs. frequency
 $RL = 16\ \Omega$ in-phase, $V_{CC} = 2.5\ V$

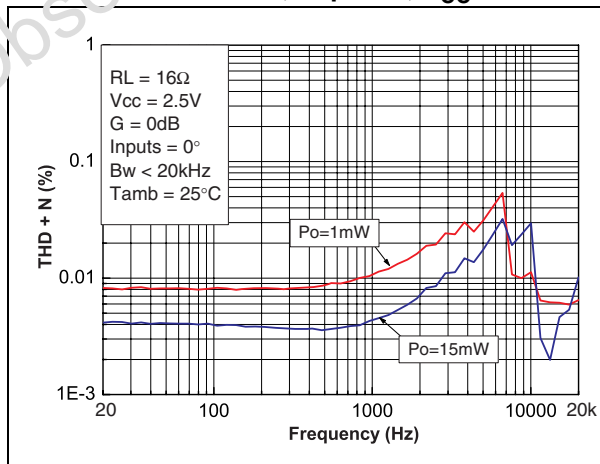


Figure 39. THD+N vs. frequency
 $RL = 16\ \Omega$ out-of-phase, $V_{CC} = 2.5\ V$

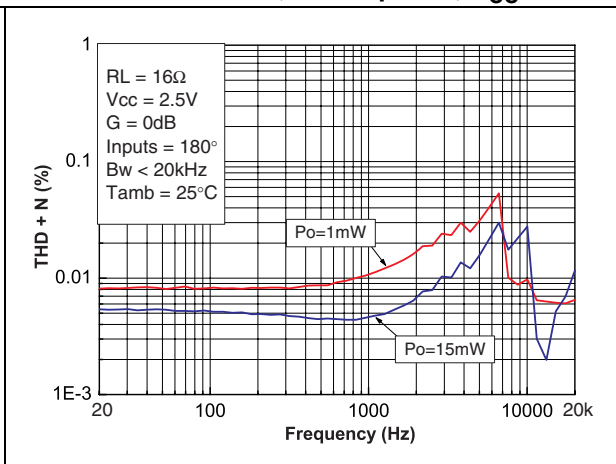


Figure 40. THD+N vs. frequency
RL = 16 Ω in-phase, V_{CC} = 3.6 V

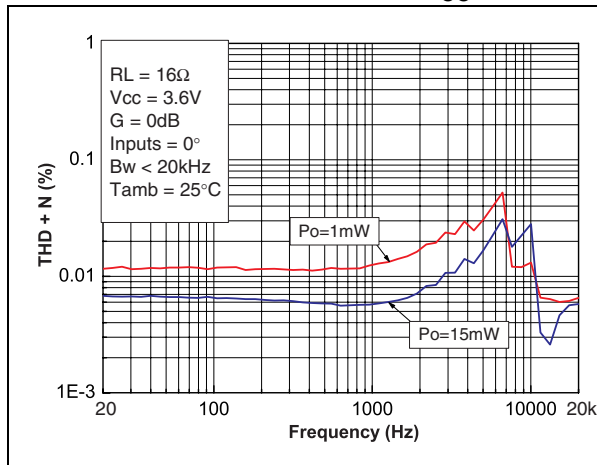


Figure 41. THD+N vs. frequency
RL = 16 Ω out-of-phase, V_{CC} = 3.6 V

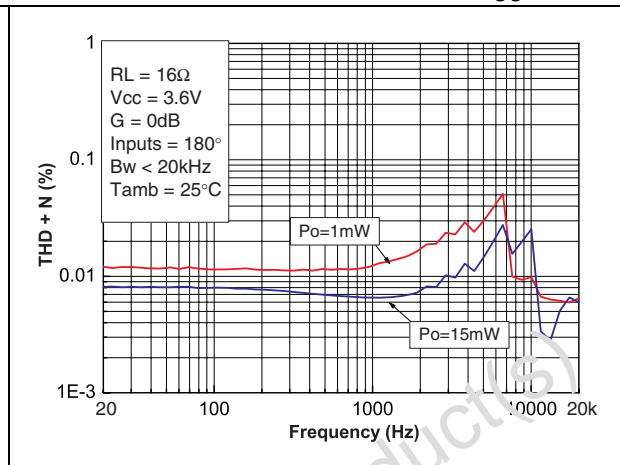


Figure 42. THD+N vs. frequency
RL = 16 Ω in-phase, V_{CC} = 4.8 V

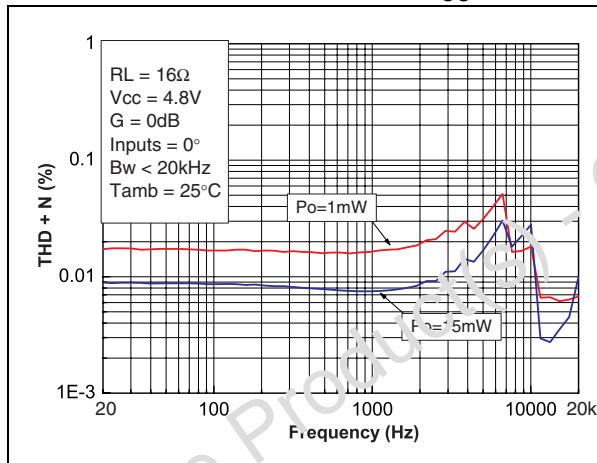


Figure 43. THD+N vs. frequency
RL = 16 Ω out-of-phase, V_{CC} = 4.8 V

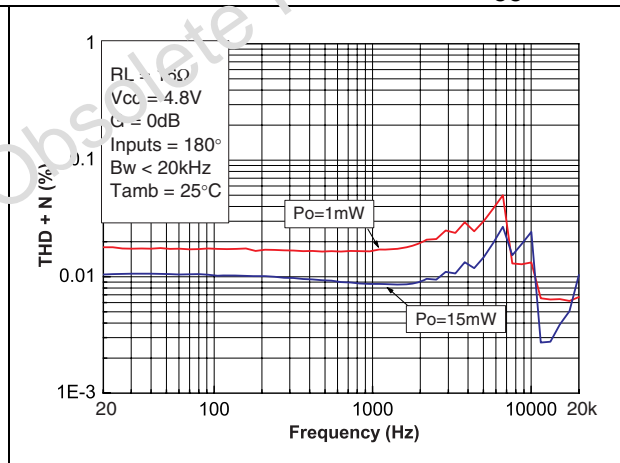


Figure 44. THD+N vs. frequency
RL = 32 Ω in-phase, V_{CC} = 2.5 V

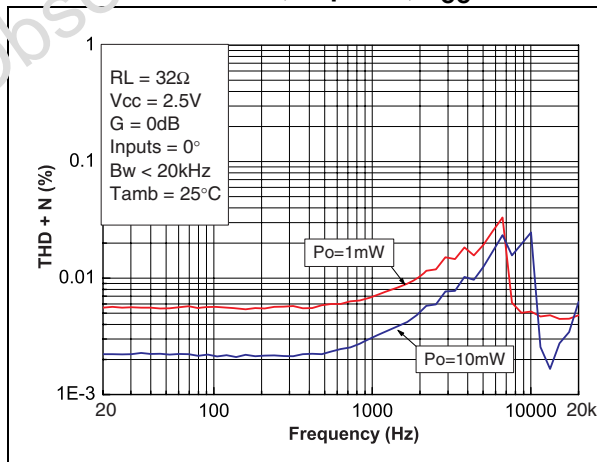


Figure 45. THD+N vs. frequency
RL = 32 Ω out-of-phase, V_{CC} = 2.5 V

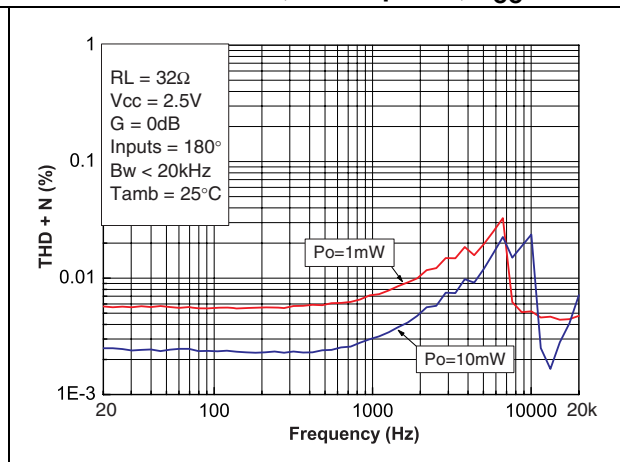


Figure 46. THD+N vs. frequency
RL = 32 Ω in-phase, V_{CC} = 3.6 V

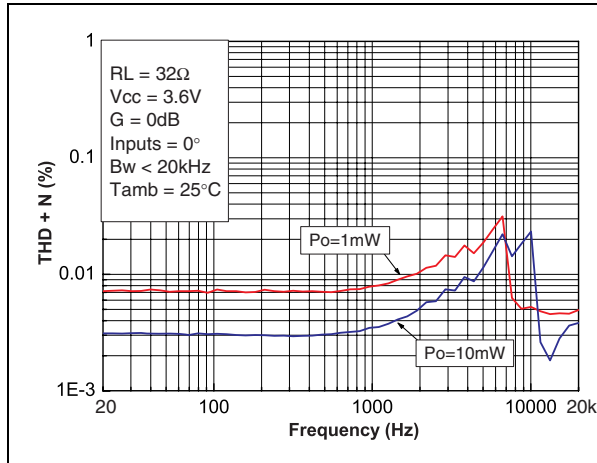


Figure 47. THD+N vs. frequency
RL = 32 Ω out-of-phase, V_{CC} = 3.6 V

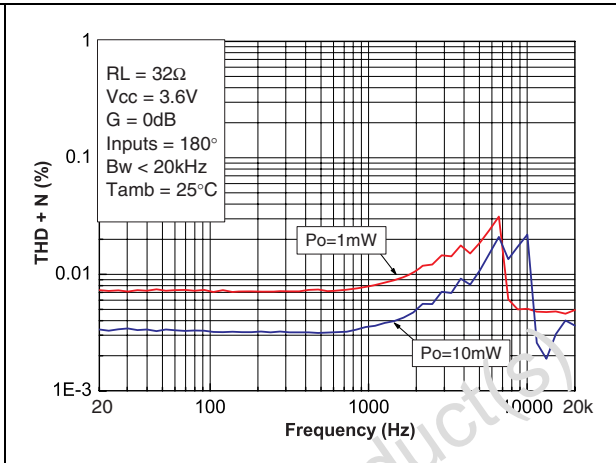


Figure 48. THD+N vs. frequency
RL = 32 Ω in-phase, V_{CC} = 4.8 V

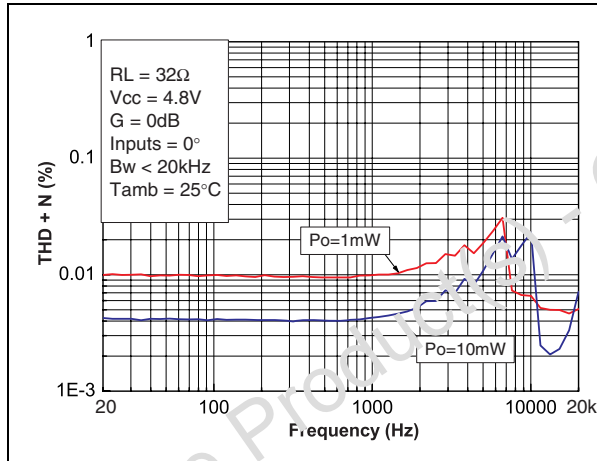


Figure 49. THD+N vs. frequency
RL = 32 Ω out-of-phase, V_{CC} = 4.8 V

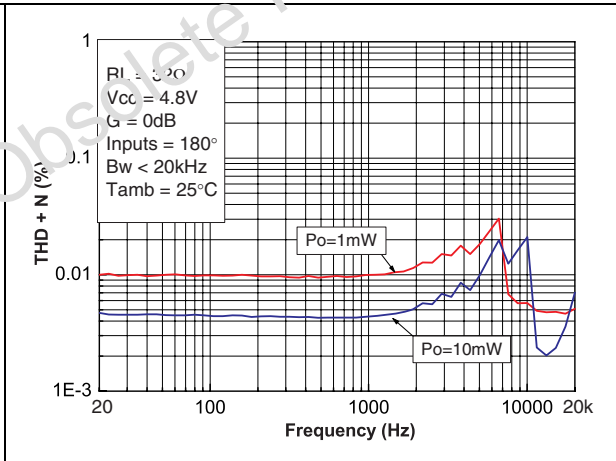


Figure 50. THD+N vs. frequency
RL = 47 Ω in-phase, V_{CC} = 2.5 V

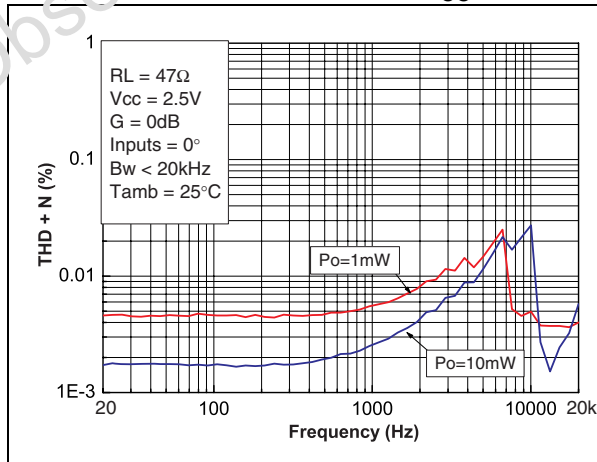


Figure 51. THD+N vs. frequency
RL = 47 Ω out-of-phase, V_{CC} = 2.5 V

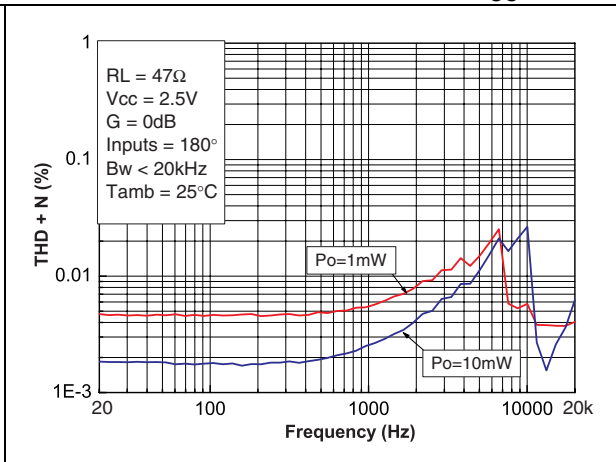


Figure 52. THD+N vs. frequency
 $RL = 47\ \Omega$, in-phase, $V_{CC} = 3.6\ V$

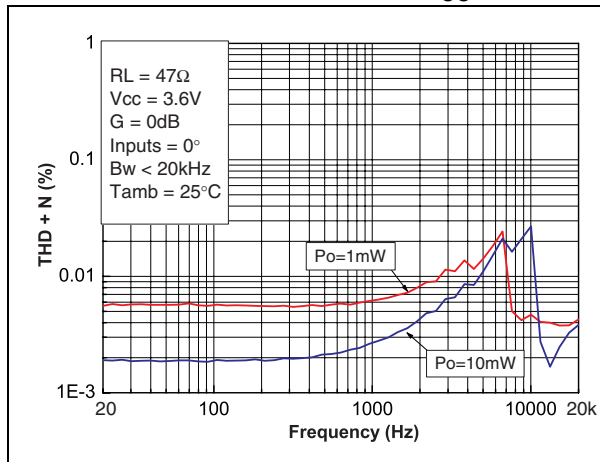


Figure 53. THD+N vs. frequency
 $RL = 47\ \Omega$, out-of-phase, $V_{CC} = 3.6\ V$

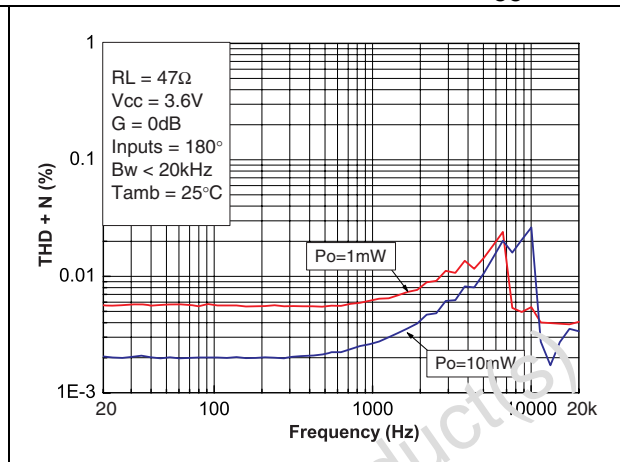


Figure 54. THD+N vs. frequency
 $RL = 47\ \Omega$, in-phase, $V_{CC} = 4.8\ V$

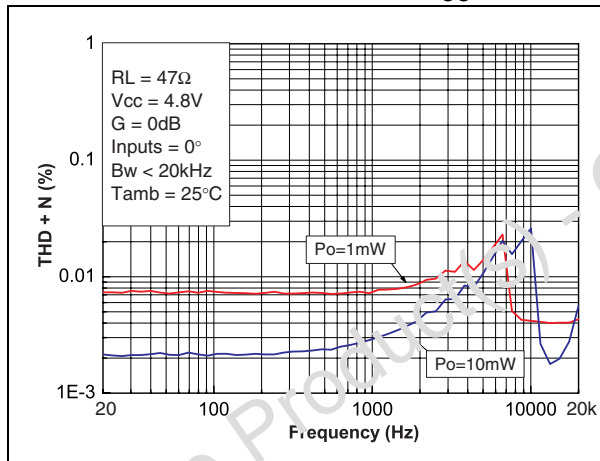


Figure 55. THD+N vs. frequency
 $RL = 47\ \Omega$, out-of-phase, $V_{CC} = 4.8\ V$

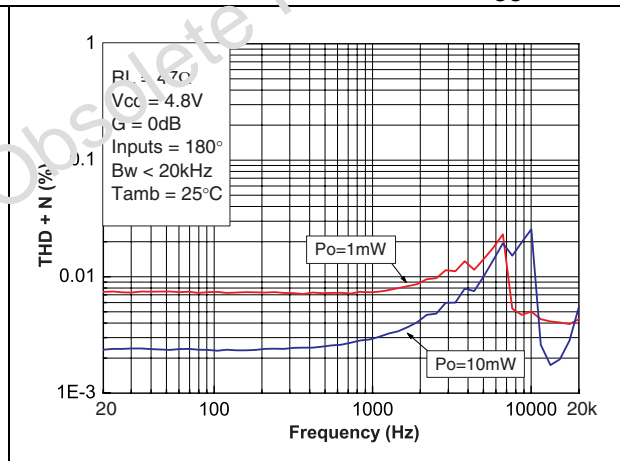


Figure 56. THD+N vs. frequency
 $RL = 10\ k\Omega$

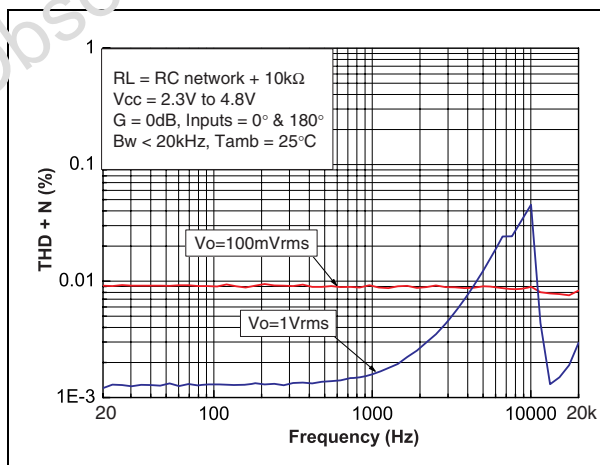


Figure 57. THD+N vs. frequency
 $RL = 600\ \Omega$

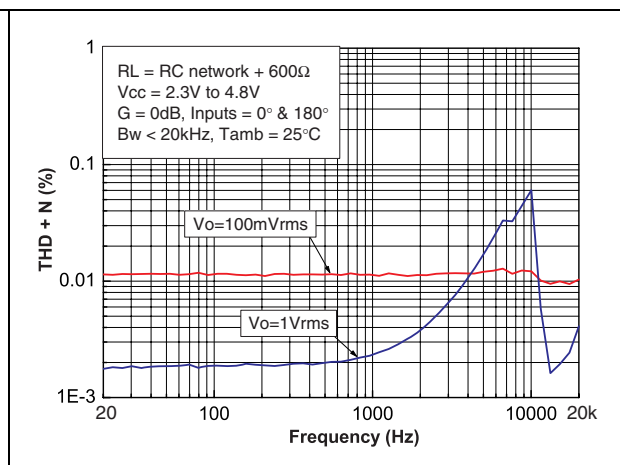


Figure 58. THD+N vs. output voltage
 $R_L = 10\text{ k}\Omega$

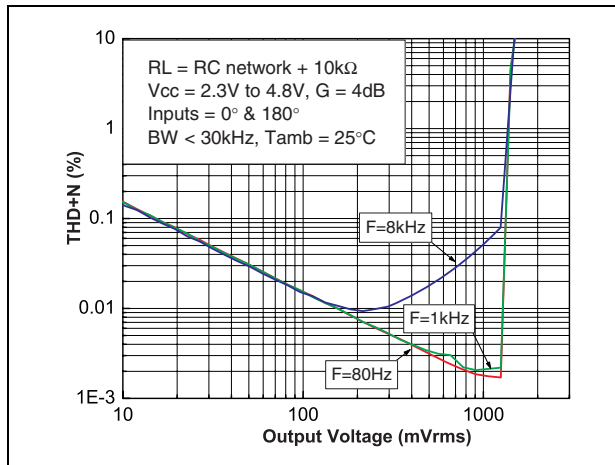


Figure 59. THD+N vs. output voltage
 $R_L = 600\ \Omega$

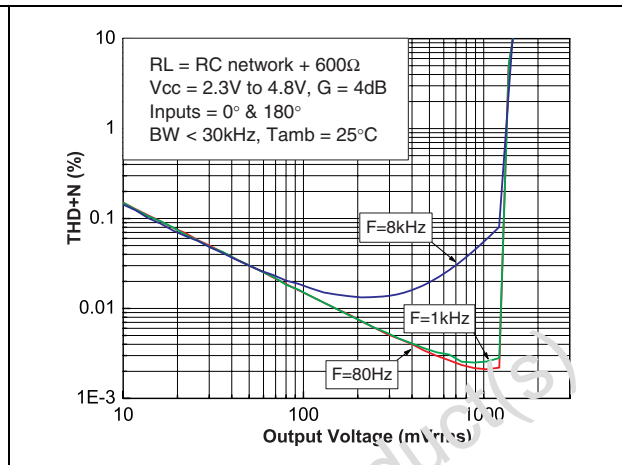


Figure 60. THD+N vs. input voltage, HiZ left and right

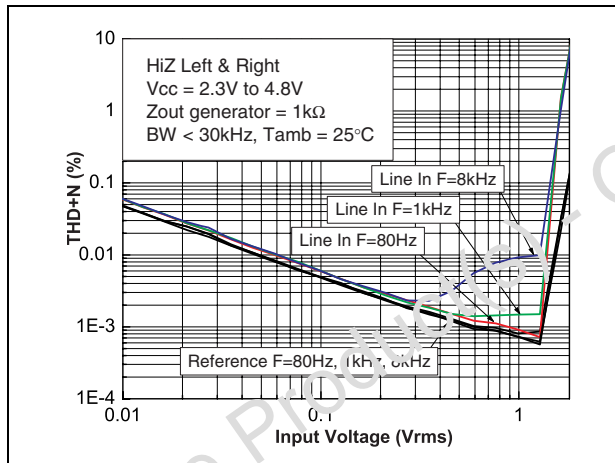


Figure 61. CMRR vs. frequency

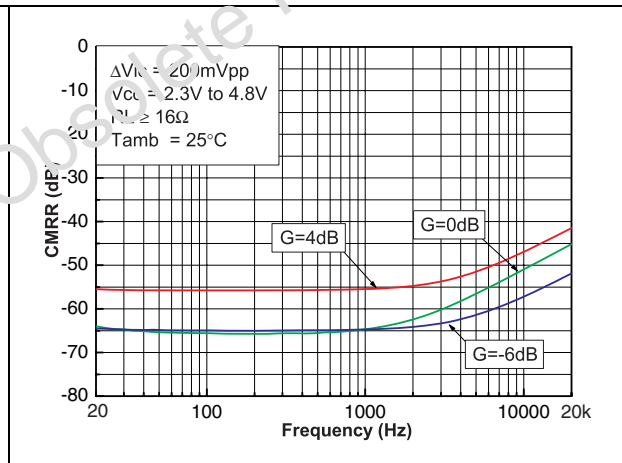


Figure 62. PSRR vs. frequency
 $V_{CC} = 2.5\text{ V}$

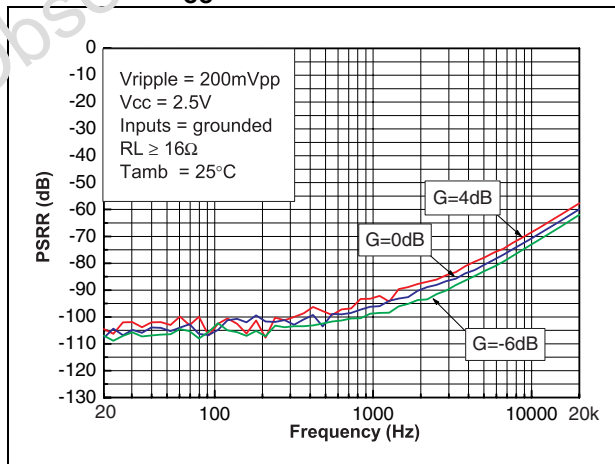


Figure 63. PSRR vs. frequency
 $V_{CC} = 3.6\text{ V}$

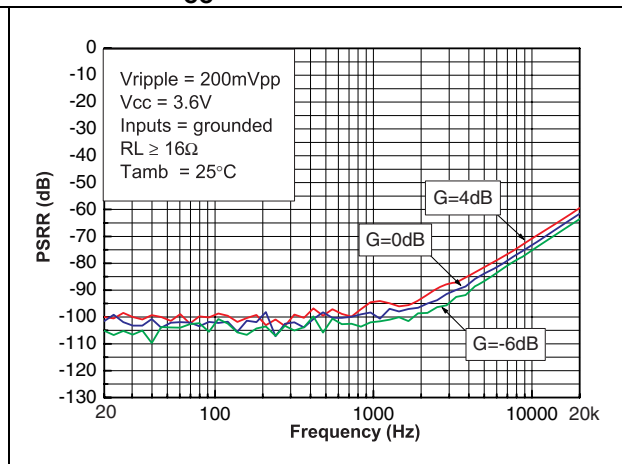


Figure 64. PSRR vs. frequency
 $V_{CC} = 4.8\text{ V}$

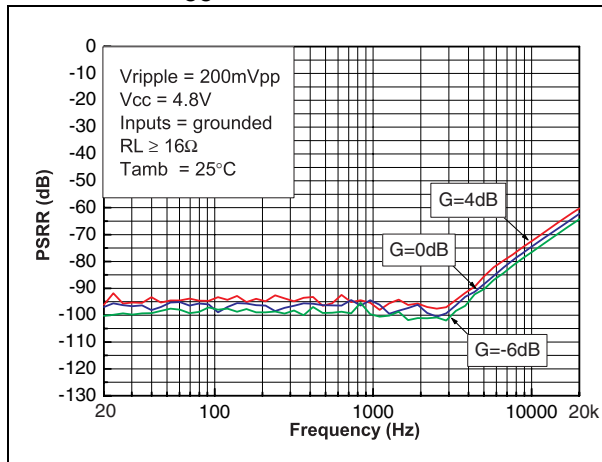


Figure 65. Output signal spectrum

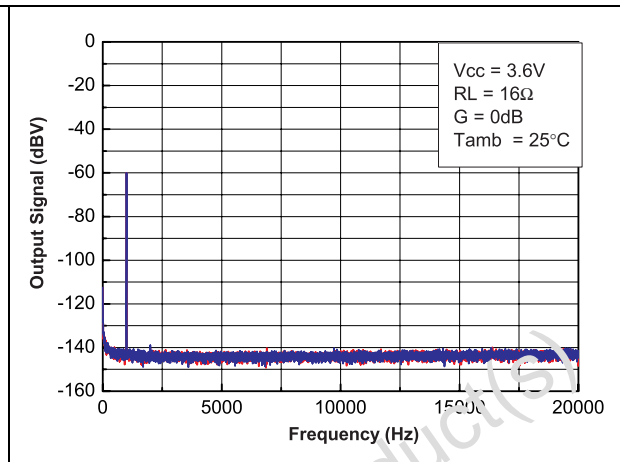


Figure 66. Crosstalk vs. frequency
 $RL = 16\ \Omega$

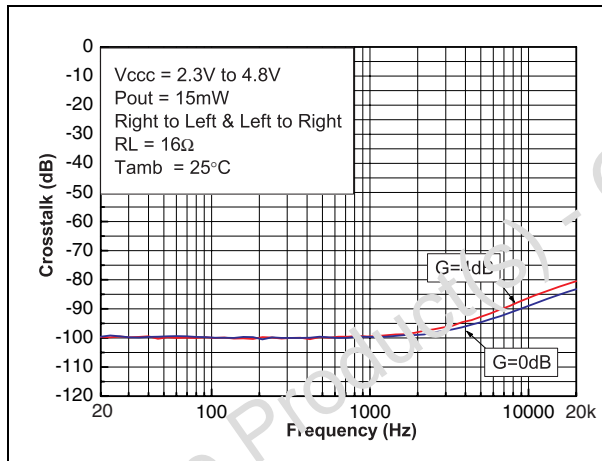


Figure 67. Crosstalk vs. frequency
 $RL = 32\ \Omega$

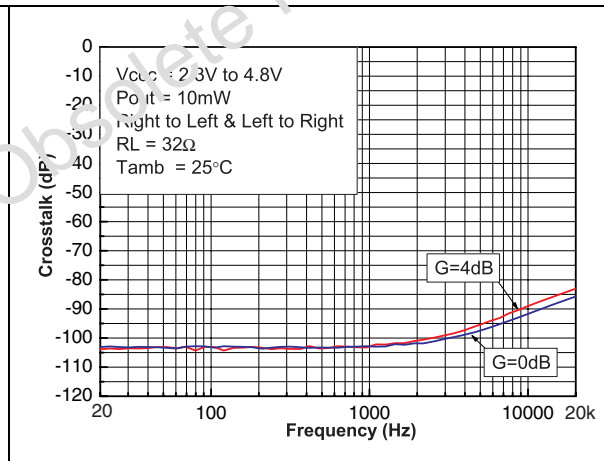


Figure 68. Crosstalk vs. frequency
 $RL = 47\ \Omega$

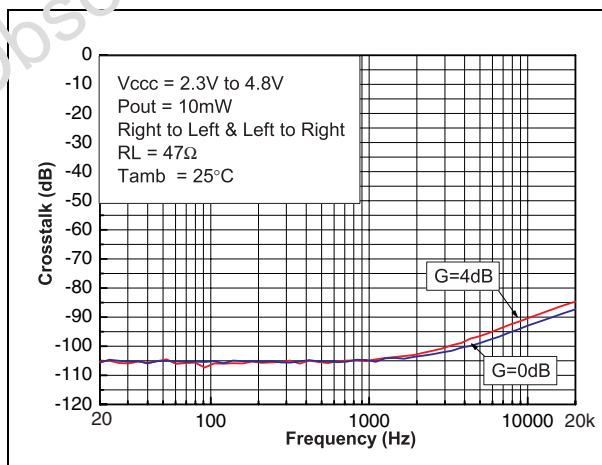


Figure 69. Crosstalk vs. frequency
 $RL = 10\ \text{k}\Omega$

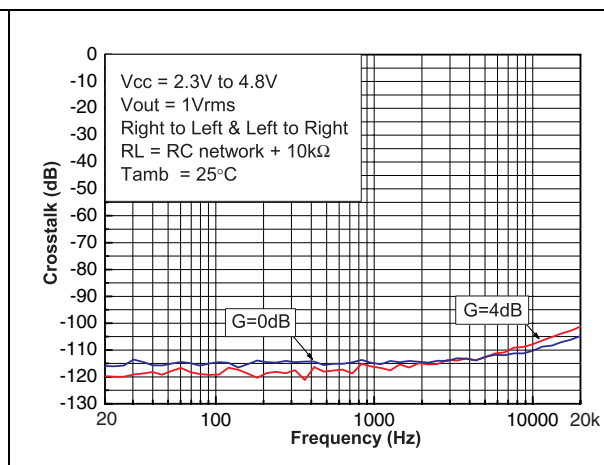


Figure 70. Wake-up time

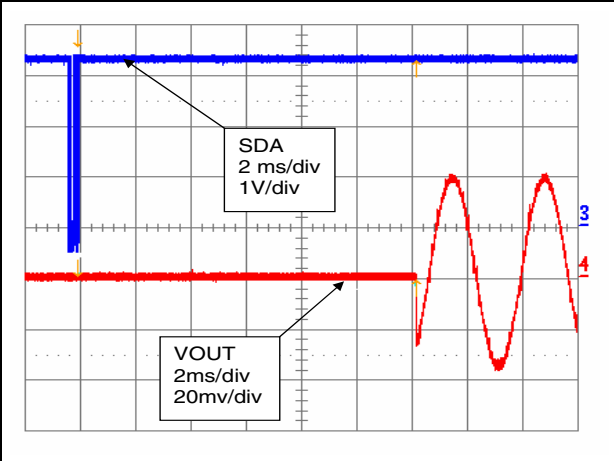
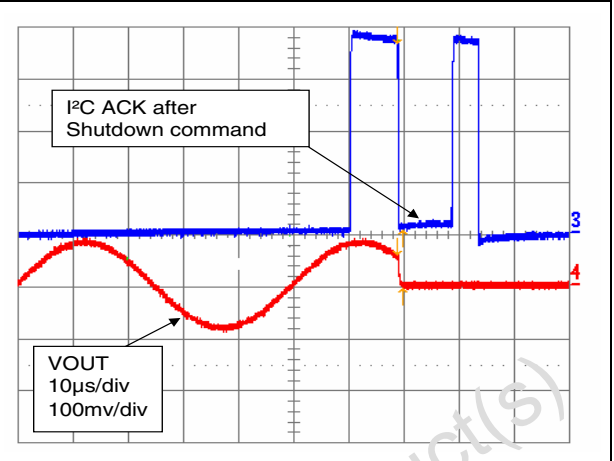


Figure 71. Shutdown time



4 Application information

4.1 I²C bus interface

In compliance with the I²C protocol, the TS4621 uses a serial bus to control the chip's functions with the clock (SCL) and data (SDA) wires. These two lines are bi-directional (open collector) and require an external pull-up resistor (typically 10 kΩ). The maximum clock frequency in fast mode specified by the I²C standard is 400 kHz, which the TS4621 supports. In this application, the TS4621 is always the slave device and the controlling microcontroller MCU is the master device.

The slave address of the TS4621 is 1100 000x (C0h).

[Table 8](#) summarizes the pin descriptions for the I²C bus interface.

Table 8. Pin description of the I²C bus interface

Pin	Functional description
SDA	Serial data pin
SCL	Clock input pin

4.1.1 I²C bus operation

The host MCU can write to the TS4621 control register to control the TS4621, and read from the control register to obtain a configuration from the TS4621. The TS4621 is addressed by the byte consisting of the 7-bit slave address and the R/W bit.

Table 9. First byte after the START message for addressing the device

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	0	0	0	0	X

There are four control registers ([Table 10](#)) named CR1 to CR4. In read mode, all the control registers can be accessed. In write mode, only CR1, CR2 and CR3 can be addressed.

Table 10. Summary of control registers

Description	Register address	D7	D6	D5	D4	D3	D2	D1	D0
CR1	1	HP_EN_L	HP_EN_R	0	0	0	0	T_SH	SWS
CR2 volume control	2	Mute_L	Mute_R	Volume control					0
CR3	3	0	0	0	0	0	0	HiZ_L	HiZ_R
CR4 identification	4	0	1	0	0	0	0	0	0

Table 11. Control registers at power up

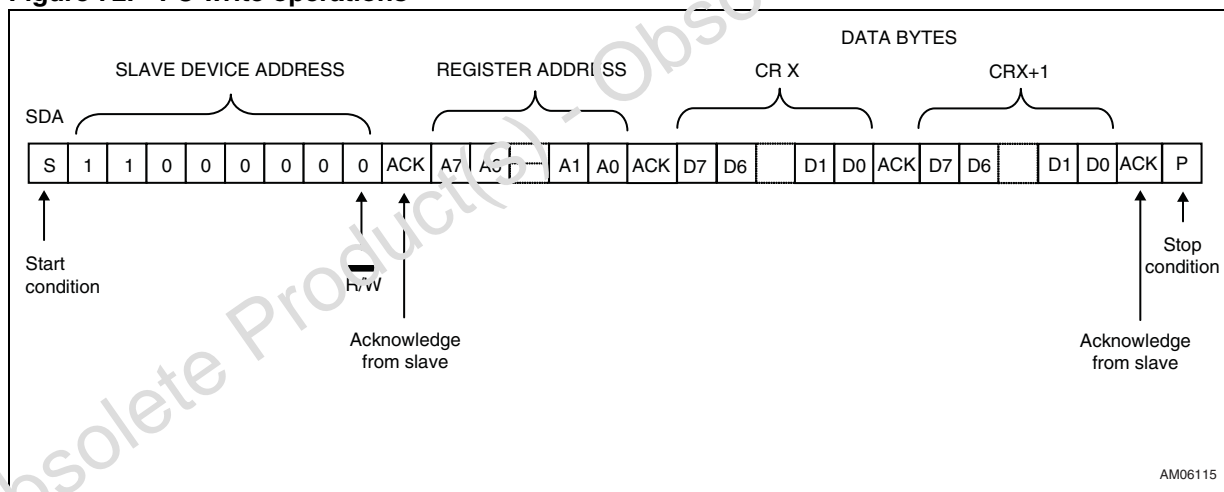
Description	Register address	D7	D6	D5	D4	D3	D2	D1	D0
CR1	1	0	0	0	0	0	0	0	1
CR2	2	1	1	0	0	0	0	0	0
CR3	3	0	0	0	0	0	0	0	0
CR4	4	0	1	0	0	0	0	0	0

Writing to the control registers

To write data to the TS4621, after the "start" message the MCU must:

- send the I²C 7-bit slave address and a low level for the R/W bit.
- send the register address to write to.
- send the data bytes (control register settings).

All bytes are sent MSB first. The transfer of written data ends with a "stop" message. When transmitting several data bytes, the data can be written without having to repeat the "start" message or send the byte with the slave address. If several bytes are transmitted, they will be written repeatedly to CR1, CR2 and CR3.

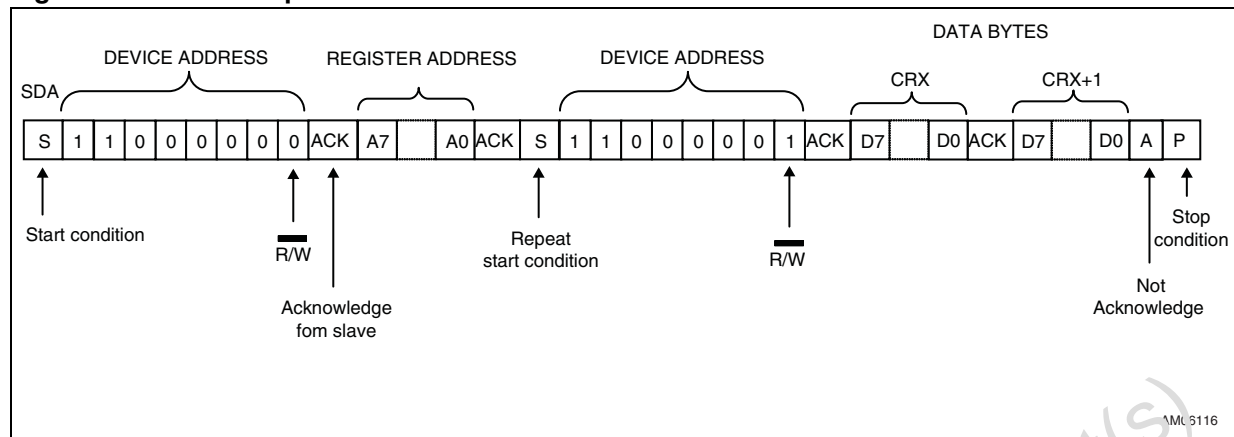
Figure 72. I²C write operations

Reading from the control registers

To read data from the TS4621, after the "start" message the MCU must:

- send the I²C 7-bit slave address and a low level for the R/W bit.
- send the register address to read.
- send the I²C 7-bit slave address and a high level for the R/W bit.
- receive the data (control register value).

All bytes are read MSB first. The transfer of read data ends with a "stop" message. When transmitting several data bytes, the data can be read without having to repeat the "start" message or send the byte with the slave address. If several bytes are transmitted, they are read repeatedly from CR1, CR2, CR3 and CR4.

Figure 73. I²C read operations

4.1.2 Control register CR1 - address 1

Software shutdown: bit SWS

When SWS equals 1, the device is set to I²C software shutdown. When SWS equals 0, the negative supply and the internal DC/DC step-down converters are activated.

Caution: When the TS4621 is in standby mode, the AVdd and SW pins are connected together with an impedance of approximately 1 kΩ. This means that the HpVdd pin is set to the Vbat voltage through the L1 inductor. Consequently, the minimum standby current is only reached when the Ct capacitor is fully charged to Vbat ($1 \text{ k}\Omega \times 10 \text{ }\mu\text{F} \times 5 = 50 \text{ ms}$ maximum).

Channel activation: bits HP_EN_L and HP_EN_R

When HP_EN_L or HP_EN_R equals 1, the corresponding amplifier channel is enabled.

Thermal shutdown protection: bit T_SH

A thermal shutdown protection is implemented to protect the device from overheating. If the temperature rises above the thermal junction of 150°C, the device is put into standby mode and a flag is raised in the read register CR1.

T_SH: equals 0 during normal operation, equals 1 when a thermal shutdown is detected.

When the temperature decreases to safe levels, the circuit switches back to normal operation and the corresponding flag is cleared.

4.1.3 Control register CR2 - address 2

Table 12. Volume control register CR2 - address 2

Volume control range: -60 dB to +4 dB											
D5	D4	D3	D2	D1	Gain (in dB)	D5	D4	D3	D2	D1	Gain (in dB)
0	0	0	0	0	-60 dB	1	0	0	0	0	-11 dB
0	0	0	0	1	-54 dB	1	0	0	0	1	-10 dB
0	0	0	1	0	-50.5 dB	1	0	0	1	0	-9 dB
0	0	0	1	1	-47 dB	1	0	0	1	1	-8 dB
0	0	1	0	0	-43 dB	1	0	1	0	0	-7 dB
0	0	1	0	1	-39 dB	1	0	1	0	1	-6 dB
0	0	1	1	0	-35 dB	1	0	1	1	0	-5 dB
0	0	1	1	1	-31 dB	1	0	1	1	1	-4 dB
0	1	0	0	0	-27 dB	1	1	0	0	0	-3 dB
0	1	0	0	1	-25 dB	1	1	0	0	1	-2 dB
0	1	0	1	0	-23 dB	1	1	0	1	0	-1 dB
0	1	0	1	1	-21 dB	1	1	0	1	1	0 dB
0	1	1	0	0	-19 dB	1	1	1	0	0	+1 dB
0	1	1	0	1	-17 dB	1	1	1	0	1	+2 dB
0	1	1	1	0	-15 dB	1	1	1	1	0	+3 dB
0	1	1	1	1	-13 dB	1	1	1	1	1	+4 dB

Mute function: bits MUTE_L and MUTE_R

In the volume register, MUTE_L and MUTE_R are dedicated to enabling the mute function, independently of the channel. When MUTE_L and MUTE_R are set to 1, the mute function is enabled on the corresponding channel and the gain is set to -80 dB. When MUTE_L and MUTE_R are set to 0, the I²C gain level is applied to the channel.

4.1.4 Control register CR3 - address 3

High output impedance mode: bits HiZ_L and HiZ_R

The TS4621 features a high-output impedance mode used, for example, to share the headphone jack with the audio and composite video signal.

To set this mode, you must set the HIZ bit to 1 for the targeted output in the CR3 register.

At this time, the considered output is in high-impedance mode with the following characteristics:

- Maximum input voltage = -1.8 to +1.8 V
- Output impedance = input impedance detected by the video driver. For an example, refer to [Chapter 3: Electrical characteristics on page 10](#) or [Figure 18](#).

4.1.5 Summary of output impedance

Table 13. Summary table for output impedance vs. output mode

SWS	HiZ	HP_EN	Output impedance	Maximum voltage allowed on output pin
1	0	0	20 to 40 Ω	Less than ± 100 mV
1	0	1	20 to 40 Ω	Less than ± 100 mV
1	1	0	about 10 k Ω	-0.3 V to AVdd
1	1	1	about 10 k Ω	-0.3 V to AVdd
0	0	0	20 to 40 Ω	Less than ± 100 mV
0	0	1	Less than 1 Ω	Not applicable
0	1	0	See Figure 18	-1.8 to +1.8 V
0	1	1	See Figure 18	-1.8 to +1.8 V

4.2 Wake-up and standby time definition

The wake-up time of the TS4621 is guaranteed at 12 ms typical (refer to [Chapter 3: Electrical characteristics](#)). However, since the TS4621 is activated with an I²C bus, the wake-up start procedure is as follows.

1. The master sends a start bit.
2. The master sends the device address.
3. The slave (TS4621) answers by an acknowledge bit.
4. The master sends the register address.
5. The slave (TS4621) answers by an acknowledge bit.
6. The master sends the output mode configuration (CR1).
7. If the TS4621 was previously in standby mode, the wake-up starts on the falling edge of the eighth clock signal (SCL) corresponding to the CR1 byte.
8. After 12 ms (de-pop sequence time), the TS4621 outputs are operational.

The standby time is guaranteed as 100 μ s typical (refer to [Chapter 3](#)). However, since the TS4621 is de-activated with an I²C bus, the standby time operates as follows.

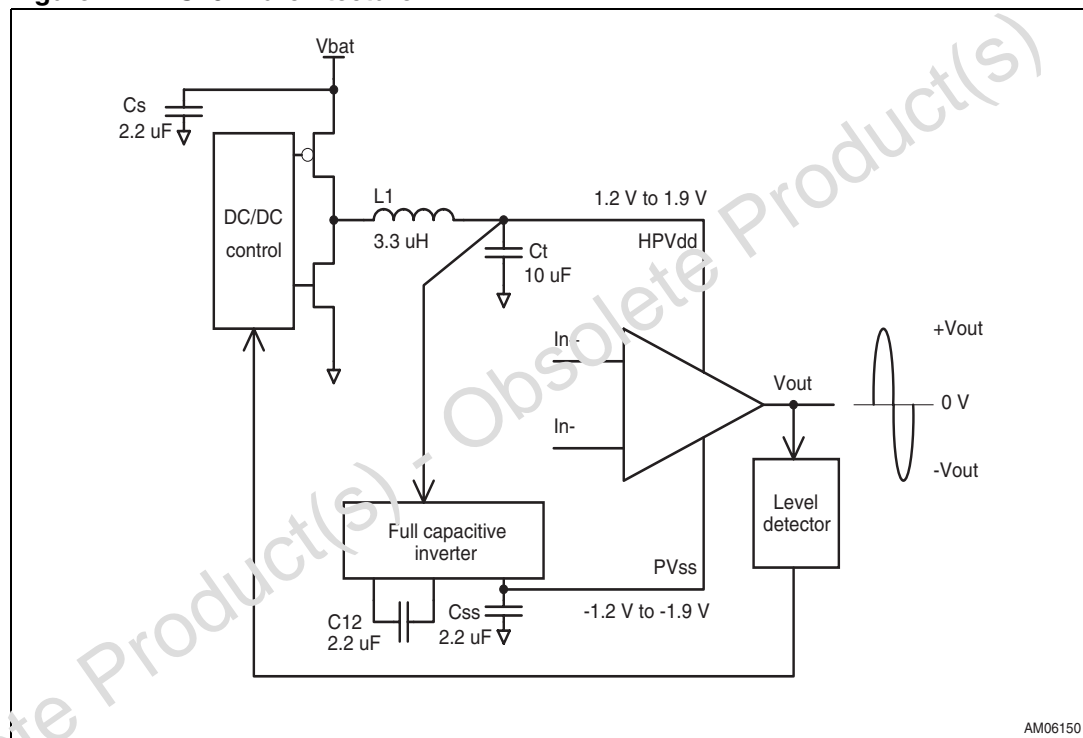
1. The master sends a start bit.
2. The master sends the device address.
3. The slave (TS4621) answers by an acknowledge bit.
4. The master sends the register address.
5. The slave (TS4621) answers by an acknowledge bit.
6. The master sends the output mode configuration (CR1), which corresponds, in this case, to standby mode.
7. The standby time starts on the falling edge of the eighth clock signal (SCL) corresponding to the CR1 byte.
8. After 100 μ s, the TS4621 is in standby mode.

4.3 Overview of the class G, 2-level headphone amplifier

The TS4621 uses what is referred to as *class G operating mode*. This mode is a combination of the class AB biasing technique and an adaptive power supply. For this device, the power supply uses two levels: ± 1.2 V and ± 1.9 V.

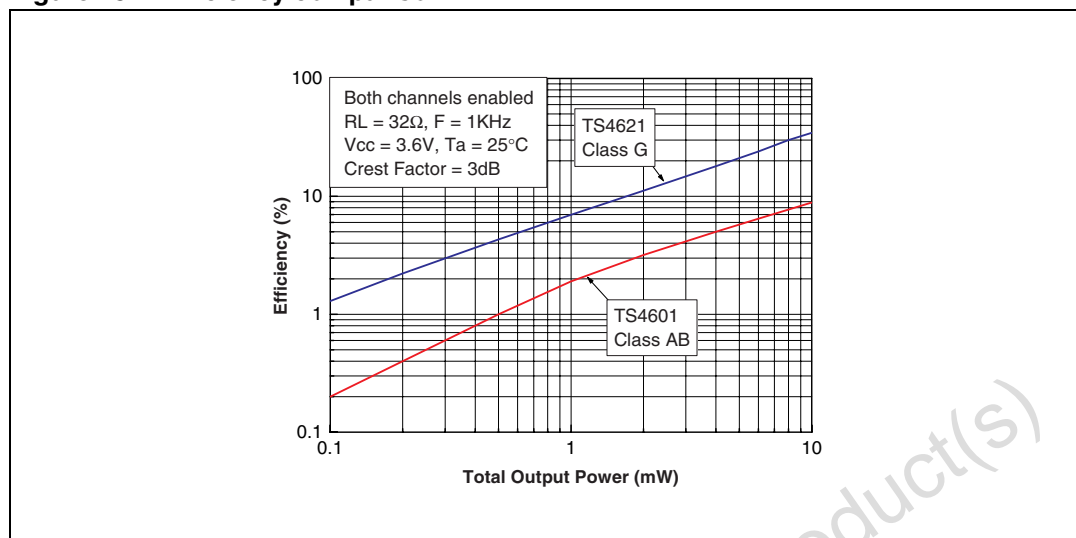
To create the ± 1.2 V and ± 1.9 V levels, the device uses an internal high-efficiency step-down converter linked with a fully capacitive inverter from AVdd. Thanks to these internally-generated symmetrical power supply voltages, the output of the amplifier can be biased at 0 V, thus eliminating the classical bulky DC blocking output capacitors (typically more than 100 μ F).

Figure 74. TS4621 architecture



When an audio signal is playing with the TS4621, the class G feature adjusts in real time the internal power supply voltage in order to achieve the best efficiency possible. In addition, thanks to the fast transient response of the internal DC/DC converters, the switching between ± 1.2 V and ± 1.9 V can be achieved without audio clipping. Moreover, the out-of-audio band DC/DC switching frequency keeps the audio quality at a high level (distortion, noise, etc...).

Figure 75. Efficiency comparison

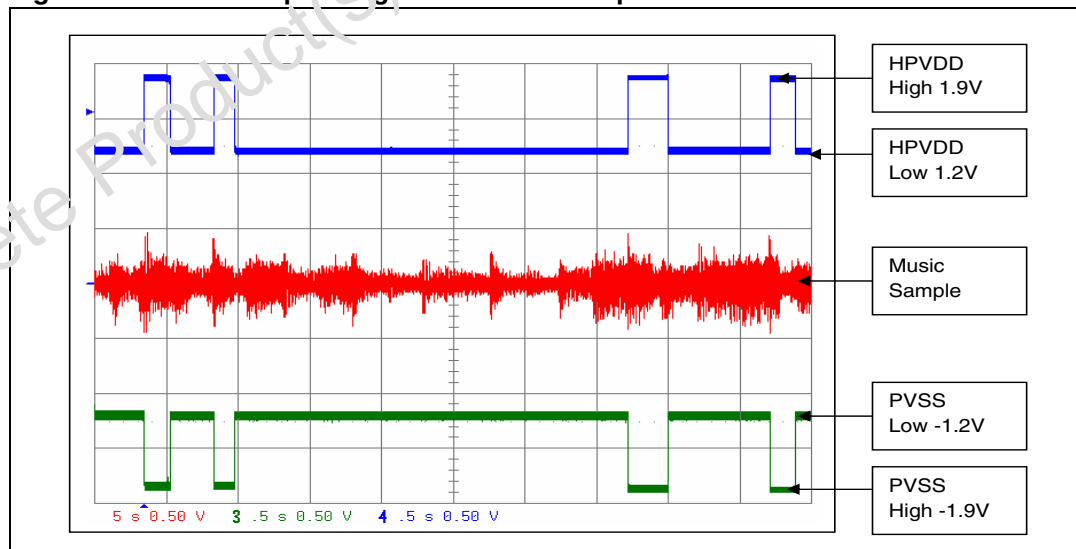


Most audio signals have a crest factor higher than 6 dB (10 dB on average), which means that most of the time the music level is low. In this case, the setting of the internal DC/DC converters is low (1.2 V) and in this way, helps to minimize the power dissipation.

When the audio signal amplitude increases due to a peak or louder music, the setting of the internal DC/DC converters increases to 1.9 V, automatically increasing the output dynamic range. This 1.9 V value remains until the end of the decay time.

Figure 76 shows a music sample played at high levels.

Figure 76. Class G operating with a music sample



Note: HPVDD/PVSS voltages are created internally by DC/DC converters. To avoid destruction of the TS4621 power amplifier, do not connect any external power supply on these pins.

4.4 External component selection

The TS4621 requires few external passive components to operate correctly. Each component is described in the following sections.

4.4.1 Step-down inductor selection (L1)

The TS4621 needs one inductor for the internal step-down DC/DC converter. This inductor must fit the following constraints:

- Typical value: 2.2 μH to 3.3 μH (3.3 μH is recommended).
- Maximum current in operating mode: 400 mA
- Minimum inductor value at maximum current: 1.5 μH
- Maximum inductor value at zero current: 4.3 μH
- DC resistance: from 50 m Ω up to 450 m Ω

Table 14 shows the part number that should be used according to the inductor value.

Table 14. Recommended inductor

Manufacturer	Part number	Value
Murata	LQM21PN3R3NGRD	3.3 μH
	LQM2MPN3R3C0L	3.3 μH
	LQM2MPN2R2G0L	2.2 μH
FDK	MIPSZ2012D3R3	3.3 μH
	MIPSZ2012D2R2	2.2 μH

4.4.2 Step-down output capacitor selection (Ct)

For the internal DC/DC step-down converter, the TS4621 needs one output capacitor.

The three criteria for selecting the output capacitor are the range value of the capacitor including self tolerance, DC variation and the minimum ESR value, which is mandatory to avoid oscillation of the converter. Therefore the following constraints must be observed.

- Typical capacitor value: 10 μF at DC = 0 V
- Maximum capacitor value: 12 μF at DC = 0 V
- Minimum capacitor value: 4.8 μF at DC = 2 V
- Voltage range across this capacitor: from 1.1 V to 2 V
- Minimum DC ESR value: 5 m Ω

A ceramic capacitor in a 0603-type package is also recommended because of its close placement to the TS4621, which makes it easier to minimize parasitic inductance and resistance that have a negative impact on the audio performance.

Table 15. Recommended capacitor

Manufacturer	Part number	Value
Murata	GRM188R60J106ME47	10 μ F, 6.3 V, X5R
	GRM188R60J106ME84	10 μ F, 6.3 V, X5R
	GRM188R61E106ME73	10 μ F, 25 V, X5R

4.4.3 Full capacitive inverter capacitors selection (C12 and C_{ss})

Two capacitors (C12 and C_{ss}) are needed for this internal DC/DC inverter.

The three criteria for selecting these capacitors are the range value of the capacitor including self tolerance, DC variation and the minimum ESR to minimize power losses.

- Typical capacitor value: 2.2 μ F +/-20 %
- Voltage across these capacitors: from 1.1 V to 2 V
- Minimum capacitor value: 1 μ F

Again, a ceramic capacitor in a 0603 or 0402-type package is also recommended because of their close placement to the TS4621, which makes it easier to minimize parasitic inductance and resistance that have a negative impact on the audio performance.

4.4.4 Power supply decoupling capacitor selection (C_s)

A 2.2 μ F decoupling capacitor with low ESR is recommended for positive power supply decoupling. Packages such as the 0402 or 0603 are also recommended because of their close placement to the TS4621, which makes it easier to minimize parasitic inductance. It is advised to choose a X5R dielectric for capacitor tolerance, and a 10 V DC rating voltage for 4.8 V operations (or a 6.3 V DC rating voltage for 3.6 V operations), to take into consideration the $\Delta C/V$ variation of this type of ceramic capacitor.

An important parameter is the rated voltage of the capacitor. A 2.2 μ F/6.3 V capacitor used at 4.8 V DC typically loses about 40 % of its value. In fact, with a 4.8 V power supply voltage, the decoupling value is about 1.3 μ F instead of 2.2 μ F. Because the decoupling capacitor influences the THD+N in the medium-to-high frequency region, this capacitor variation becomes decisive. In addition, less decoupling means higher overshoots, which can be problematic if they reach the power supply's AMR value (5.5 V). This is why, for a 2.2 μ F value, we recommend a 2.2 μ F/10 V, a 4.7 μ F/6.3 V or a ceramic capacitor with a low DC bias variation rated at 6.3 V.

4.4.5 Input coupling capacitor selection (C_{in})

C_{in} input coupling capacitors are mandatory for the TS4621's operation. They block any DC component coming from the audio signal source.

C_{in} with R_{in} form a first-order high-pass filter and the -3 dB cut-off frequency is:

$$FC(-3dB) = \frac{1}{2 \times \pi \times R_{in} \times C_{in}}$$

R_{in} is the single-ended input impedance that can be approximated at about R_{indiff}/2.

R_{in} also depends on the gain setting. [Figure 19](#) provides the differential input impedance vs. gain. One can also see that R_{indiff} is minimum for the maximum gain setting (that is, 4 dB).

Therefore, in most cases, R_{in} should be set to 4 dB to calculate the minimum input capacitor C_{in} .

Example:

At maximum gain $G = 4$ dB, $R_{indiff}/2 = k\Omega/2 = 17\text{ k}\Omega$. However, to take into consideration the worst case, one has to use $R_{indiff}/2 = 25\text{ k}\Omega/2 = 12.5\text{ k}\Omega$.

In this case and for a -3 dB cut-off frequency of 20 Hz, $C_{in} = 0.64\text{ }\mu\text{F}$. The closest normalized value is 0.68 μF but a 1 μF capacitor is more suitable to take into consideration the capacitor tolerance +/-20 %.

If the aim is to have the 20 Hz at -1 dB, the capacitor has to be multiplied by 1.96. As such, $C_{in} = 0.64 \times 1.96 = 1.25\text{ }\mu\text{F}$. The closest normalized value would be 1.5 μF or 2.2 μF .

4.4.6 Low-pass output filter (R_{out} and C_{out}) and IEC 61000-4-2 ESD protection

The TS4621 is designed to operate with a passive first-order low-pass filter (as shown in [Figure 1.](#)). This low-pass filter is mandatory to ensure correct operation of the TS4621 over the volume range and output capacitance range vs. load.

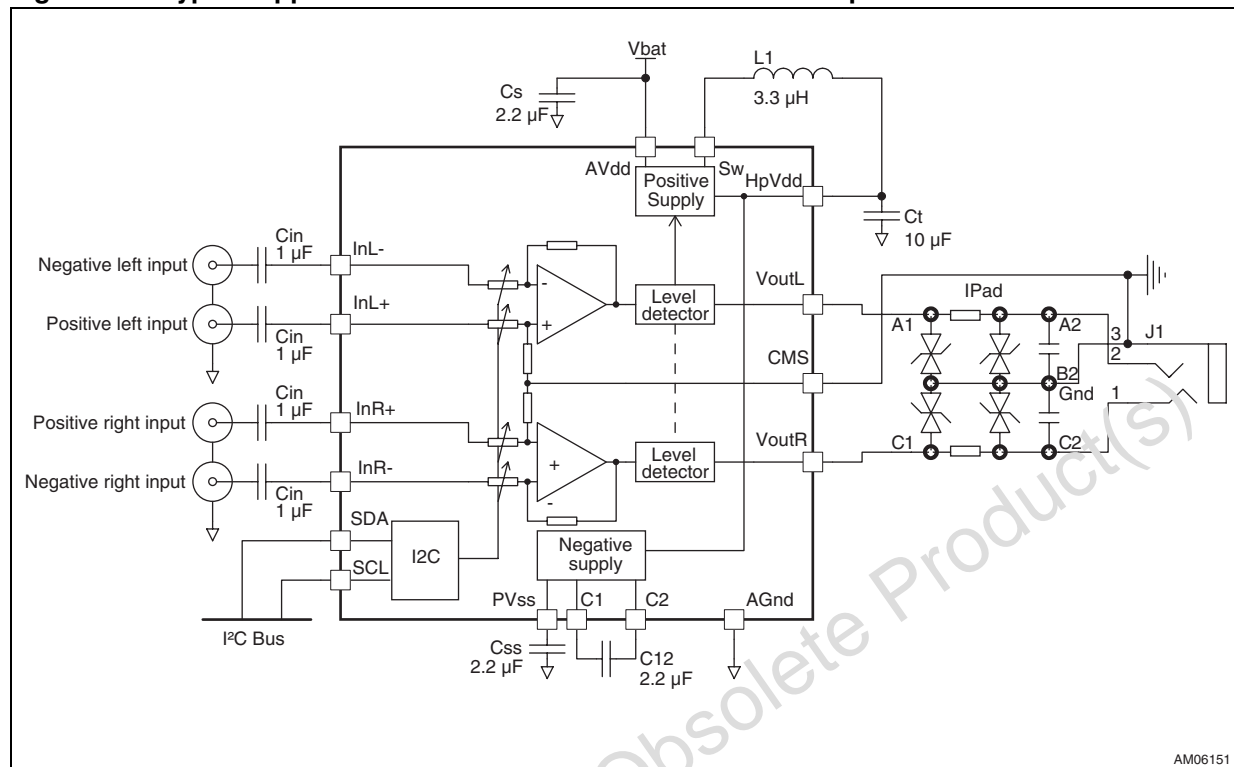
R_{out} must have a value of 12 Ω minimum and C_{out} a value of 0.8 nF minimum up to 100 nF maximum. Values of 12 Ω and 1 nF are a good starting point for a design to be able to drive a classic headphone (16 Ω , 32 Ω , 60 Ω) and the line-in of any Hi-fi system or sound card. The cut-off frequency of this filter (12 Ω and 1 nF) is approximately 13 MHz and clearly above the audio band.

However, this output RC filter is also a part of the IEC 61000-4-2 ESD protection. In most cases, this RC filter is designed with transient absorbers and the final solution can be a discrete solution or an integrated solution. ST Microelectronics' portfolio has many integrated solutions for ESD, but one dedicated to headphone amplifiers in particular: IPAD^(a) reference EMIF02-AV01F3.

To fit the IEC 61000-4-2 standard, this audio line IPAD can be added to the output of the TS4621 as shown in [Figure 77](#).

a. Copyright STMicroelectronics.

Figure 77. Typical application schematic with IEC 61000-4-2 ESD protection



By adding this ESD protection, the TS-1921 complies with the IEC 61000-4-2 level 4 standard on jack pins. Our demonstration board has been tested using the same conditions as those outlined in the IEC 61000-4-2 standard. Results may differ depending on the layout of the PCB.

- 15 kV (air discharge)
- 8 kV (contact discharge)

This LPAF has an internal series resistor $R_{out} = 15 \, \Omega \pm 20 \, \%$ and an output capacitor $C_{out} = 3.2 \, nF \pm 25 \, \%$.

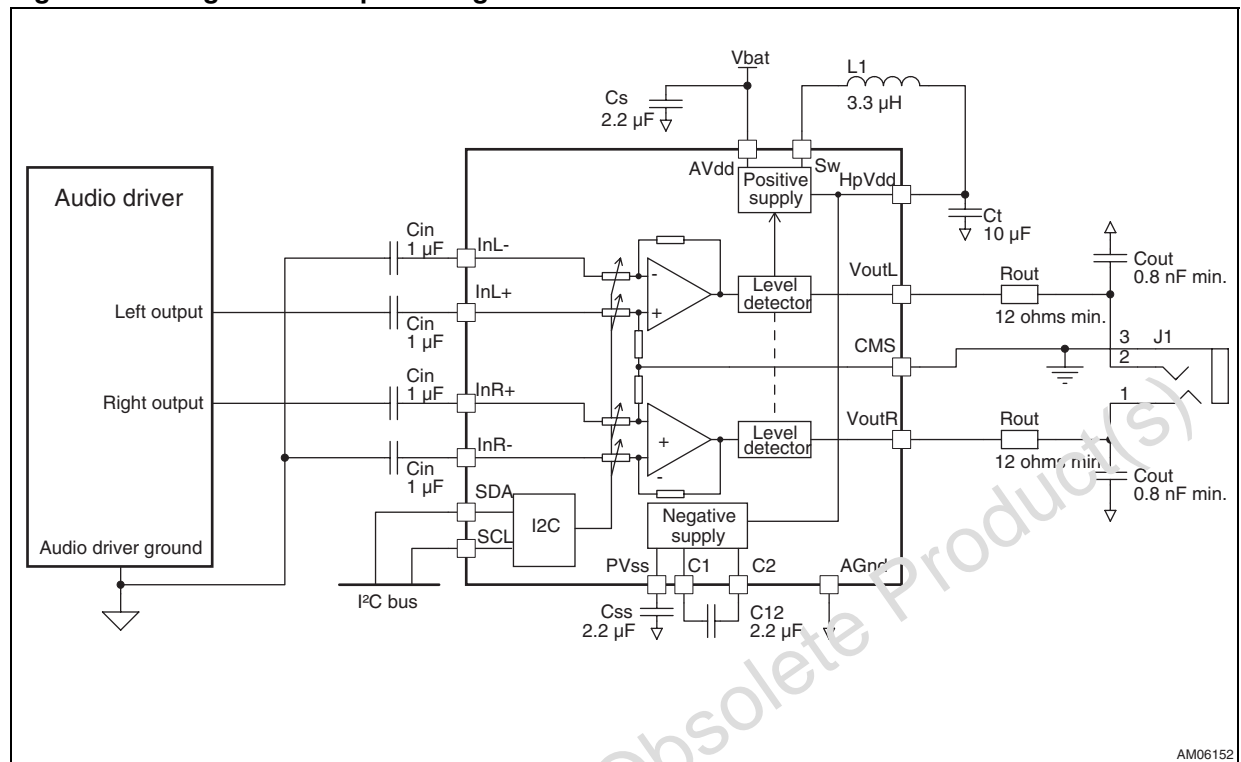
4.4.7 Integrated input low-pass filter

The TS4621 has an integrated internal first-order low-pass filter with a -3 dB cut-off frequency set at 65 kHz and independent of the volume position. This integrated filter is present on each input and filters any out-of-band audio noise coming from the audio source.

4.5 Single-ended input configuration

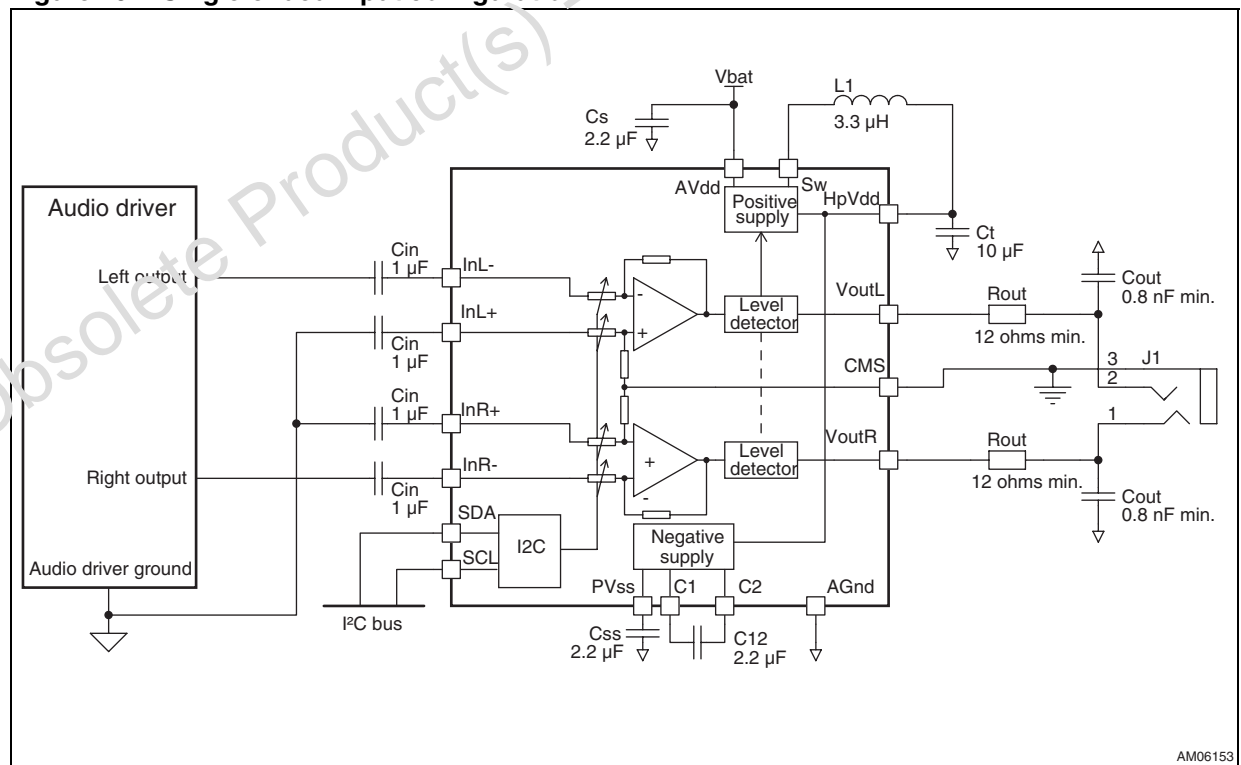
The TS4621 can be used in a single-ended input configuration. InR- and InL- or InR+ and InL+ can be shorted to ground through input capacitors. All Cin capacitors must have the same value to keep the same PSRR performance as in a differential input configuration. [Figure 78](#) and [Figure 79](#) show how to connect the TS4621. Note the ground connection of each input. To avoid PSRR issues resulting from any ground noise, this connection must be done on the ground of the audio source and not on the ground of the TS4621 itself.

Figure 78. Single-ended input configuration1



AM06152

Figure 79. Single-ended input configuration 2



AM06153

The gain range in these configurations remains unchanged and is given by:

$$V_{outLR} = V_{inLR} \times \text{Gain}$$

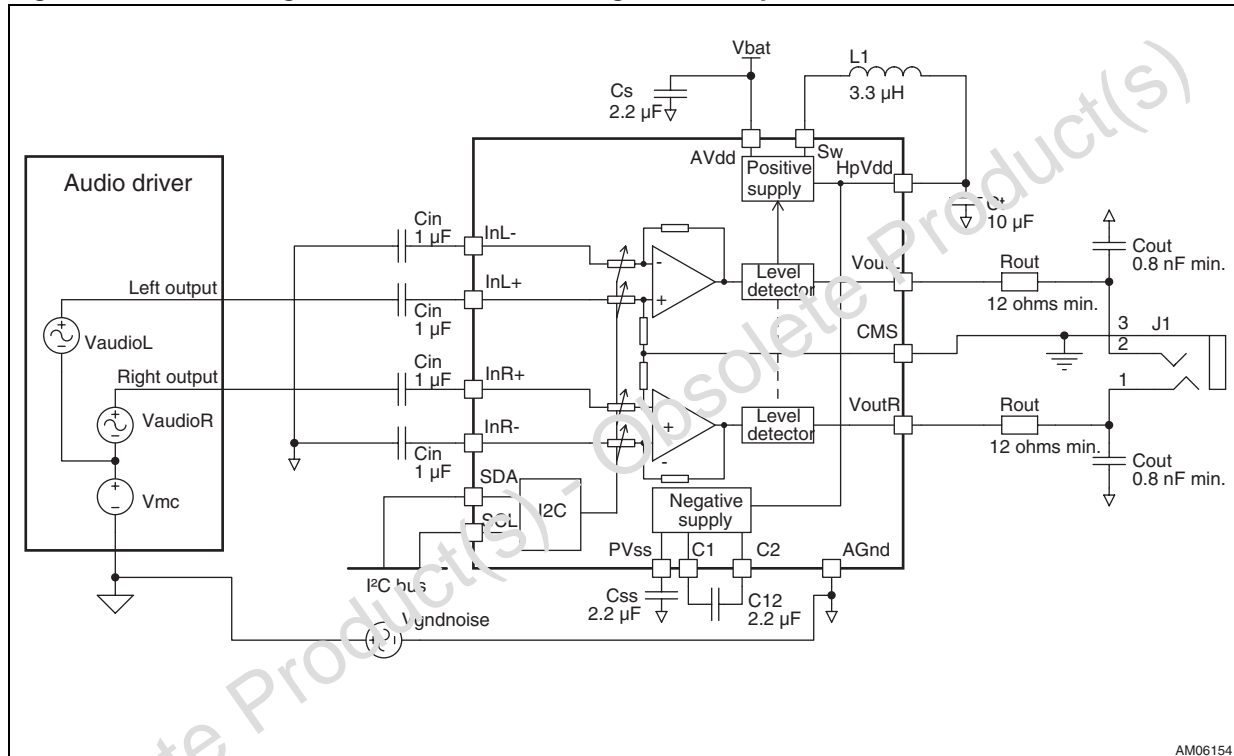
With reference to [Figure 79](#), note that the absolute phase in the audio band is 180°.

4.5.1 Layout recommendations for single-ended operation

The connection location of each input that has to be set to ground is extremely important.

Incorrect connection location

Figure 80. Incorrect ground connection for single-ended option



If these inputs are connected to AGnd (the ground of the TS4621 class G), the output voltage can be expressed by the following simplified equation from an AC point of view.

$$V_{out} = A_v \times (V_{audio} + V_{mc} + V_{gndnoise}) + V_{batnoise} \times PSRR \quad (1)$$

As shown in Equation (1), any ground noise and any parasitic AC voltage on Vmc is directly multiplied by the gain of the amplifier. If Vmc can be totally controlled by the design of the audio source device (no parasitic AC voltage), it is not necessarily the case for Vgndnoise. This noise can be significantly reduced by an adequate low impedance ground plane, but not totally eliminated. In practice, only ten millivolts in the right frequency range are enough to produce an audible parasitic sound in the headphone with a volume level as low as -20 dB.

4.6 Startup phase

The TS4621 uses different techniques to reduce the DC current consumption and offer a pop-and-click performance close to none.

4.6.1 Auto zero technology

During the start-up phase, the differential output voltage is sensed and adjusted to 0 V ($\pm 500 \mu\text{V}$) to avoid any pop noise when the amplifier becomes operational. This also helps to minimize extra current consumption due to the load ($I_{\text{cc-extra}} = V_{\text{outDC}} / R_{\text{load}}$).

4.6.2 Input impedance

The TS4621 requires input coupling capacitors. The usual lowest frequency used for the headphone is close to 20 Hz. This frequency means a constant time for a first-order high-pass filter of approximately $1 / (2 \times \pi \times 20) = 8 \text{ ms}$.

To achieve 95 % of the capacitor's charge, it is necessary to wait $3 \times 8 \text{ ms} = 24 \text{ ms}$, which is out of range for a device with a fast start-up time.

Because of the mismatching of all input capacitors and input resistors, if it is decided to start the TS4621 at a time of 8 ms, a voltage difference at the inputs (multiplied by the gain) can create a voltage step on the output and consequently a pop noise.

To avoid this issue during the starting phase, the TS4621 accelerates the charging of the input capacitors by reducing the input impedance to $2 \text{ k}\Omega$.

In such a case, for a $1 \mu\text{F}$ capacitor the 95 % charge is reached in 6 ms. As the start-up time of TS4621 is 12 ms, there remains sufficient time to fully charge the input capacitors and as such eliminate any pop noise.

4.7 Layout recommendations

Particular attention must be given to the correct layout of the PCB traces and wires between the amplifier, load and power supply (in most cases, the battery of the cellular phone).

The power and ground traces are critical since they must provide adequate energy and grounding for all circuits. Good practice is to use short and wide PCB traces to minimize voltage drops and parasitic inductance.

A track with a width of at least $200 \mu\text{m}$ for a copper thickness of $18 \mu\text{m}$ is recommended for bringing energy to the amplifier from the battery.

Proper grounding guidelines help improve audio performances, minimize crosstalk between channels, and prevent switching noise from coupling into the audio signal. It is also recommended to use a large-area and multi-via ground plane to minimize parasitic impedance.

A multi-layer PCB board allows double or multiple ground planes to be implemented. Most of the time, the top and bottom layers are used as ground planes and provide shielding for tracks routed on the intermediate layers. In addition, to minimize parasitic impedance over the entire surface, a multi-via technique that connects the bottom and top layer ground planes together in many locations is often used.

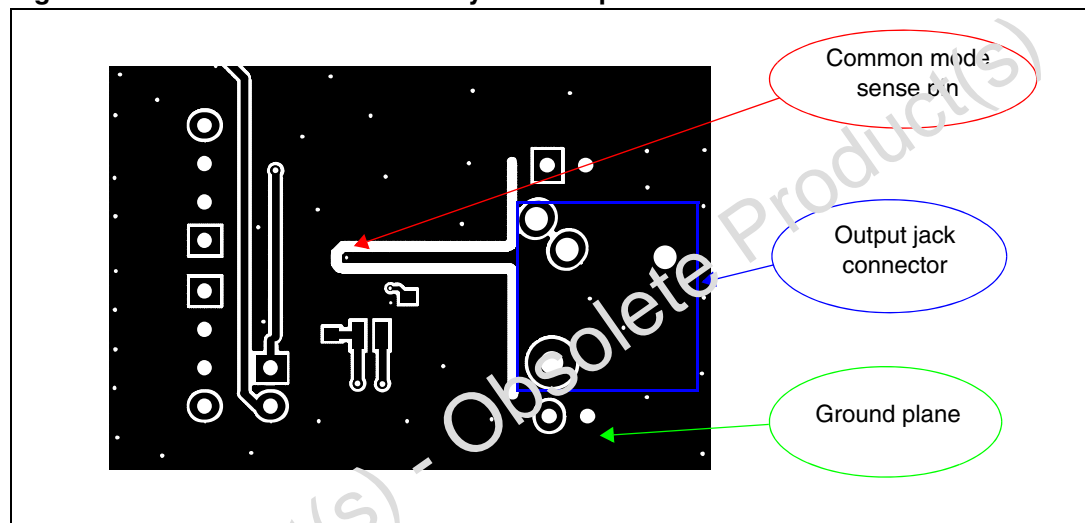
The copper traces that connect the output pins to the load and supply pins should be as wide as possible to minimize the trace resistances.

4.7.1 Common mode sense layout

The TS4621 implements a common-mode sense pin to correct any voltage differences that might occur between the return of the headphone jack and the AGND of the device that can create parasitic noise in the headphone and/or line out.

The solution to strongly reduce and practically eliminate this noise consists in connecting the headphone jack ground to the CMS pin. This pin senses the difference of potential (voltage noise) between the TS4621 ground and the headphone ground. Thanks to the frequency response and the attenuation of the common-mode sense pin, this noise is removed from the TS4621 outputs.

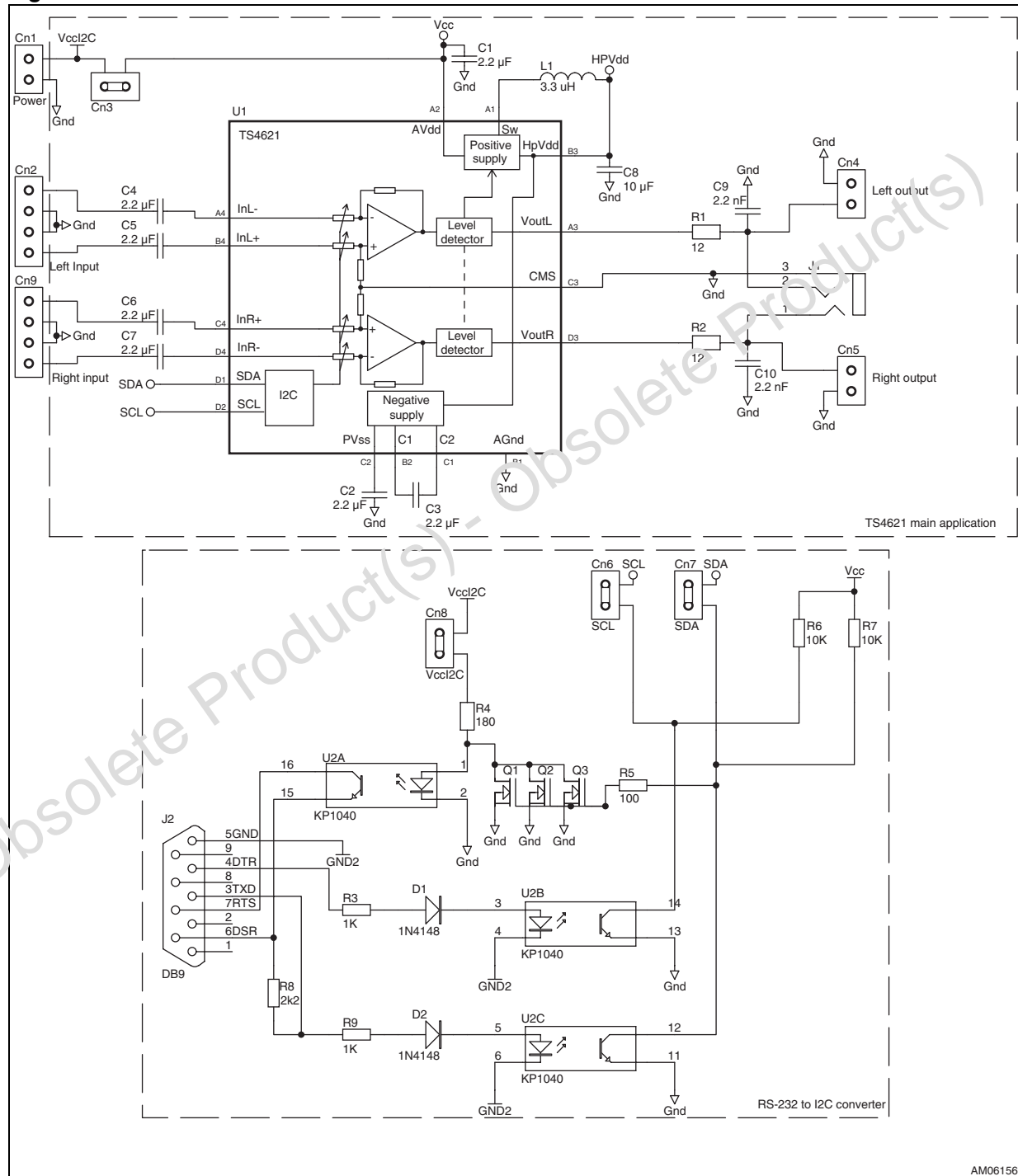
Figure 82. Common mode sense layout example



4.8 Demonstration board

A demonstration board is available at www.st.com with the order code STEVAL-CCA025V1. The following figures show the demonstration board schematics and associated PCB layouts.

Figure 83. Demonstration board schematic



AM06156

Top layer

Mid layer 1

Mid layer 2

[illegible]

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 86. TS4621 footprint recommendation

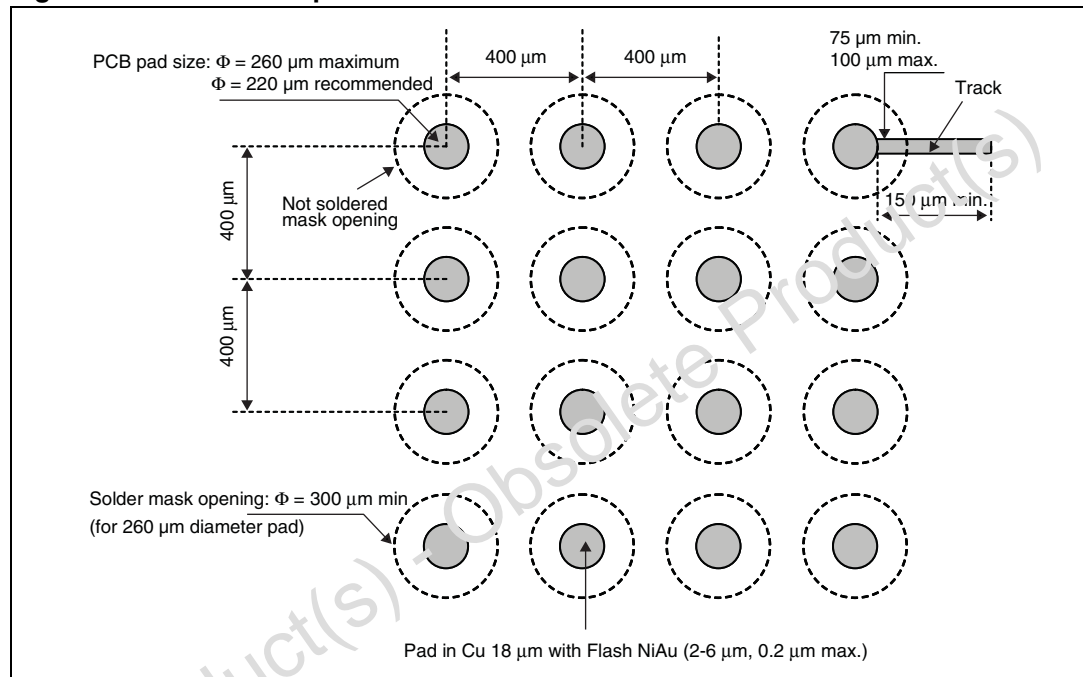
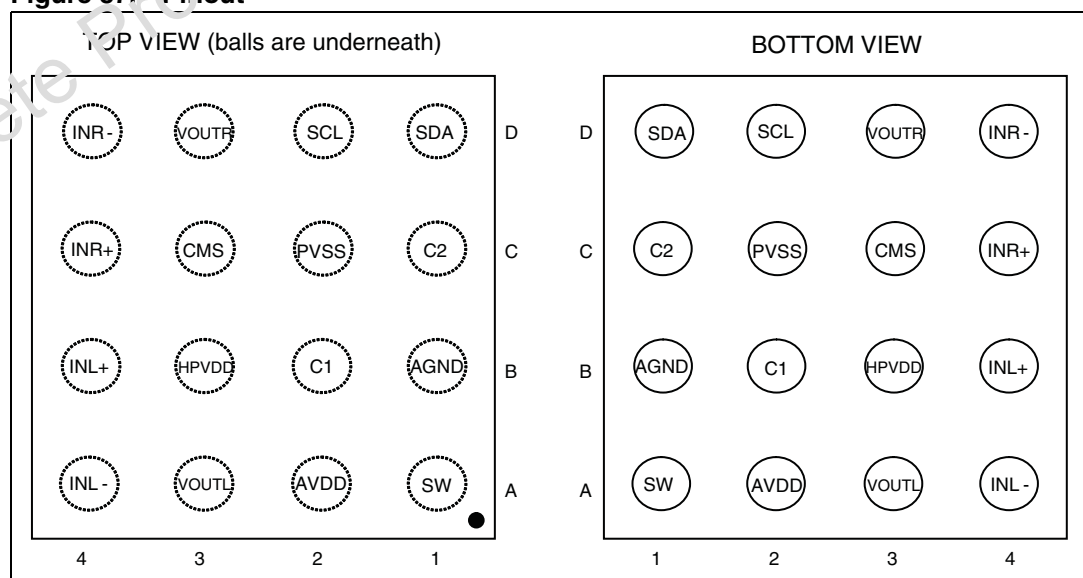


Figure 87. Pinout



- Logo: ST
- Symbol for lead-free: E
- Part number: 21
- X digit: Assembly code
- Date code: YWW
- The dot marks pin A1

■ Die size: 1.65 mm x 1.65 mm \pm 30 μ m
 ■ Die height (including bumps): 600 μ m \pm 55 μ m
 ■ Bump diameter: 250 μ m \pm 40 μ m
 ■ Bump height: 205 μ m \pm 35 μ m
 ■ Die height: 395 μ m \pm 20 μ m
 ■ Pitch: 400 μ m \pm 40 μ m
 ■ Coplanarity: 50 μ m max

Technical drawing of a die casting mold layout. The layout shows two identical dies arranged side-by-side. Each die contains a 4x4 grid of 16 circular cavities. The layout includes the following dimensions and labels:

- 8**: Total width of the mold assembly.
- 4**: Distance between the centers of the two dies.
- 1.5**: Distance from the center of a die to the outer edge of the mold.
- Die size $X + 70 \mu m$** : Width of each die.
- Die size $Y + 70 \mu m$** : Height of each die.
- A**: Label for the top-left cavity in each die grid.
- 1**: Label for the top-left cavity in each die grid.
- User direction of feed**: Indicated by a dashed arrow pointing to the right.

All dimensions are in mm.

6 Ordering information

Table 16. Order codes

Order code	Temperature range	Package	Packing	Marking
TS4621BEIJT	-40°C to +85°C	Flip-chip	Tape & reel	21

7 Revision history

Table 17. Document revision history

Date	Revision	Changes
12-Feb-2010	1	Initial release.
06-Dec-2010	2	Updated Chapter 4: Application information .

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com